



# 电子元器件系列

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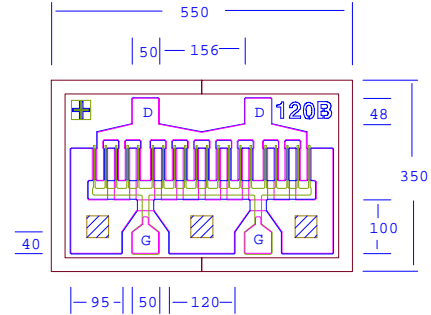


# EFA120B/EFA120BV

## DATA SHEET

### Low Distortion GaAs Power FET

- +28.0dBm TYPICAL OUTPUT POWER
- 9.5dB TYPICAL POWER GAIN FOR EFA120B AND 11.5dB FOR EFA120BV AT 12GHz
- 0.3 X 1200 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- EFA120BV WITH VIA HOLE SOURCE GROUNDING
- Idss SORTED IN 20mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EFA120B			EFA120BV			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
P <sub>1dB</sub>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	26.0	28.0		26.0	28.0		dBm
G <sub>1dB</sub>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	8.0	9.5		10.0	11.5		dB
PAE	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>		34			36		%
I <sub>dss</sub>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	200	340	440	200	340	440	mA
G <sub>m</sub>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	140	180		140	180		mS
V <sub>p</sub>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =3.0mA		-2.0	-3.5		-2.0	-3.5	V
BV <sub>gd</sub>	Drain Breakdown Voltage I <sub>gd</sub> =1.2mA	-12	-15		-12	-15		V
BV <sub>gs</sub>	Source Breakdown Voltage I <sub>gs</sub> =1.2mA	-7	-14		-7	-14		V
R <sub>th</sub>	Thermal Resistance (Au-Sn Eutectic Attach)		40			30		°C/W

### MAXIMUM RATINGS AT 25°C

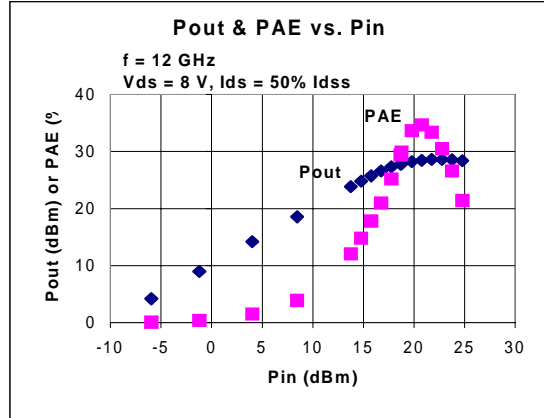
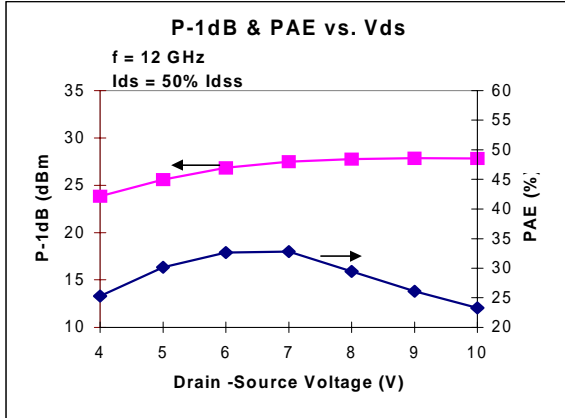
SYMBOLS	PARAMETERS	EFA120B		EFA120BV	
		ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-4V	-8V	-4V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	355mA	I <sub>dss</sub>	I <sub>dss</sub>
I <sub>gsf</sub>	Forward Gate Current	30mA	5mA	30mA	5mA
P <sub>in</sub>	Input Power	26dBm	@ 3dB Compression	26dBm	@ 3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	3.4W	2.8W	4.5W	3.8W

# EFA120B/EFA120BV

## DATA SHEET

### Low Distortion GaAs Power FET

#### EFA120B



#### S-PARAMETERS

##### EFA120B 8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.950	-67.1	8.659	139.4	0.034	55.2	0.254	-47.4
2.0	0.911	-106.2	6.163	114.7	0.047	36.7	0.222	-79.6
4.0	0.881	-138.8	3.609	89.3	0.054	21.6	0.212	-106.1
6.0	0.875	-153.5	2.524	72.4	0.053	17.5	0.251	-118.6
8.0	0.873	-163.0	1.949	58.5	0.052	14.4	0.307	-126.7
10.0	0.871	-170.7	1.573	46.1	0.047	13.8	0.370	-134.4
12.0	0.878	-180.0	1.320	32.9	0.047	12.5	0.446	-143.0
14.0	0.883	-173.1	1.105	20.5	0.045	13.1	0.521	-152.2
16.0	0.888	-165.7	0.921	7.9	0.045	12.7	0.583	-162.2
18.0	0.909	-162.3	0.775	-2.9	0.046	11.8	0.637	-172.1
20.0	0.916	-159.4	0.648	-14.2	0.049	12.9	0.685	-177.4
22.0	0.914	-160.6	0.543	-21.8	0.054	15.6	0.715	-167.3
24.0	0.933	-161.0	0.483	-28.9	0.061	20.2	0.740	-158.7
26.0	0.923	-160.0	0.419	-34.4	0.072	24.4	0.758	-152.4

##### EFA120BV 8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.937	-64.1	10.367	141.1	0.031	55.1	0.290	-50.6
2.0	0.907	-103.9	7.564	117.0	0.046	34.4	0.274	-82.9
4.0	0.887	-140.6	4.476	90.1	0.052	14.6	0.284	-110.6
6.0	0.888	-157.4	3.096	72.9	0.051	5.1	0.327	-122.1
8.0	0.892	-167.0	2.337	59.4	0.050	-0.3	0.378	-129.3
10.0	0.897	-173.6	1.864	47.5	0.048	-7.0	0.432	-135.5
12.0	0.904	-179.8	1.553	35.8	0.046	-11.6	0.483	-142.6
14.0	0.906	-174.0	1.317	24.2	0.044	-15.6	0.527	-150.2
16.0	0.911	-167.5	1.134	12.0	0.044	-21.1	0.572	-159.1
18.0	0.917	-160.9	0.975	-0.1	0.044	-25.1	0.618	-168.5
20.0	0.922	-155.1	0.837	-11.7	0.041	-30.2	0.667	-177.5
22.0	0.936	-154.0	0.702	-21.1	0.039	-31.4	0.723	-173.1
24.0	0.941	-152.0	0.603	-29.3	0.037	-31.3	0.774	-167.9
26.0	0.934	-149.5	0.530	-36.6	0.034	-24.8	0.818	-165.6

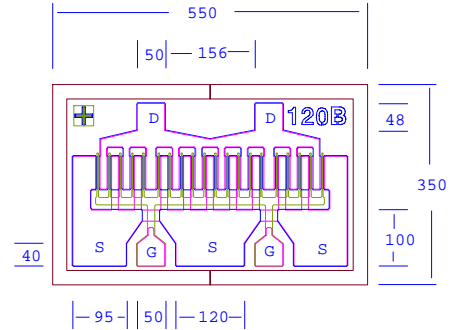
Note: The data included 0.7 mils diameter Au bonding wires; 2 gate wires, 15 mils each; 2 drain wires, 20 mils each; 6 source wires, 7 mils each; no source wires for EFA120BV.

# EFC120B

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

- +28.0dBm TYPICAL OUTPUT POWER
- 9.5dB TYPICAL POWER GAIN AT 12GHz
- HIGH BV<sub>gd</sub> FOR 10V BIAS
- 0.3 X 1200 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Id<sub>ss</sub> SORTED IN 20mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub>	26.0	28.0 28.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub>	7.5	9.5 7.0		dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub>		33		%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	160	260	360	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	100	140		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =3.0 mA		-2.5	-4.0	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =1.2mA	-15	-20		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =1.2mA	-10	-17		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		40		°C/W

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	14V	10V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4.5V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	285mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	30mA	5mA
<b>P<sub>in</sub></b>	Input Power	26dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	3.4W	2.8W

# EFC120B

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

10V, 1/2 Idss

Freq	S11	S11	S21	S21	S12	S12	S22	S22
GHz	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
1.000	0.970	-47.8	6.538	148.7	0.034	62.7	0.293	-35.9
2.000	0.928	-83.3	5.302	125.7	0.056	44.8	0.284	-63.5
3.000	0.899	-108.1	4.250	108.6	0.067	31.7	0.281	-83.1
4.000	0.884	-125.3	3.482	95.4	0.072	22.4	0.290	-95.4
5.000	0.876	-138.0	2.884	84.1	0.073	15.7	0.296	-107.6
6.000	0.868	-147.5	2.462	74.5	0.073	11.0	0.323	-114.8
7.000	0.871	-155.2	2.141	66.3	0.073	6.4	0.354	-119.3
8.000	0.866	-161.2	1.889	58.7	0.072	3.1	0.384	-123.7
9.000	0.868	-166.6	1.681	51.6	0.070	0.3	0.415	-127.2
10.000	0.871	-171.5	1.516	44.7	0.068	-2.2	0.445	-130.5
11.000	0.874	-176.7	1.380	38.1	0.066	-4.5	0.475	-134.0
12.000	0.878	179.1	1.263	31.7	0.064	-6.4	0.507	-137.2
13.000	0.878	175.3	1.159	25.4	0.063	-8.0	0.532	-140.6
14.000	0.884	172.1	1.074	19.5	0.062	-8.3	0.561	-144.4
15.000	0.885	168.4	0.992	13.5	0.060	-9.9	0.581	-148.3
16.000	0.890	164.3	0.926	6.6	0.059	-11.4	0.599	-152.8
17.000	0.890	160.9	0.862	0.5	0.059	-13.3	0.621	-158.4
18.000	0.895	158.2	0.807	-5.3	0.059	-14.0	0.644	-163.6
19.000	0.898	155.5	0.754	-11.4	0.058	-14.0	0.662	-168.7
20.000	0.905	152.1	0.703	-17.3	0.058	-13.8	0.676	-173.6
21.000	0.911	143.9	0.647	-23.3	0.056	-14.3	0.699	-172.1
22.000	0.912	141.1	0.595	-28.0	0.056	-13.1	0.713	-177.2
23.000	0.922	139.7	0.549	-33.2	0.055	-13.0	0.748	178.7
24.000	0.919	138.2	0.505	-36.9	0.054	-10.6	0.765	176.4
25.000	0.923	137.3	0.460	-40.3	0.054	-6.3	0.787	173.6
26.000	0.930	135.8	0.442	-44.3	0.056	-3.4	0.799	171.0

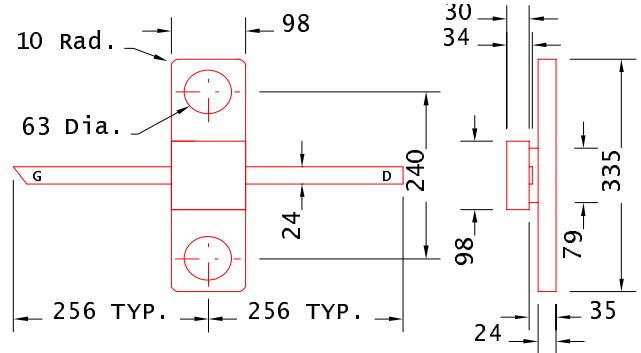
Note: The data included 0.7 mils diameter Au bonding wires:  
2 gate wires, 15 mils each; 2 drain wires, 20 mils each; 6 source wires, 7 mils each.

# EFA120B-100F

## DATA SHEET

### Low Distortion GaAs Power FET

- HERMETIC 100mil CERAMIC FLANGE PACKAGE
- +28.0dBm TYPICAL OUTPUT POWER
- 9.0dB TYPICAL POWER GAIN AT 8GHz
- 0.3 X 1200 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

All Dimensions In mils

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f = 8GHz 26.0	28.0 28.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f = 8GHz 4.0	9.0 6.0		dB
<b>PAE</b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f = 12GHz	30		%
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	200	340	440	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	140	180		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =3.0mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =1.2mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =1.2mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance		43*		°C/W

\*Overall R<sub>th</sub> depends on case mounting.

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	315mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	30mA	5mA
<b>P<sub>in</sub></b>	Input Power	26dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	3.2W	2.7W

# EFA120B-100F

## DATA SHEET

### Low Distortion GaAs Power FET

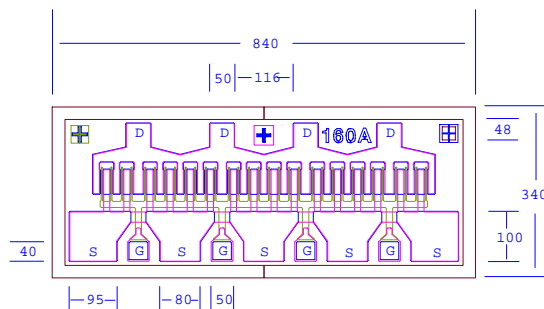
S-PARAMETERS									
8V, 1/2 Idss									
FREQ	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---		
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
1.0	0.960	-62.2	7.670	137.4	0.028	52.9	0.458	-46.5	
2.0	0.884	-102.4	5.782	106.2	0.038	34.8	0.397	-69.5	
3.0	0.841	-126.9	4.474	83.8	0.043	27.0	0.375	-85.2	
4.0	0.812	-148.4	3.697	64.4	0.047	20.8	0.376	-97.4	
5.0	0.790	-168.3	3.179	46.1	0.050	15.7	0.370	-107.9	
6.0	0.774	178.5	2.801	29.3	0.054	10.8	0.342	-125.3	
7.0	0.759	163.9	2.490	12.5	0.059	5.2	0.347	-144.3	
8.0	0.746	149.9	2.220	-3.8	0.063	-0.7	0.371	-162.5	
9.0	0.758	128.8	1.951	-20.5	0.068	-6.2	0.391	-166.2	
10.0	0.777	114.8	1.754	-35.9	0.074	-14.2	0.383	-175.9	
11.0	0.768	109.9	1.668	-51.1	0.086	-22.8	0.388	159.4	
12.0	0.740	102.0	1.596	-66.9	0.099	-32.3	0.418	142.6	
13.0	0.740	85.1	1.485	-82.4	0.114	-41.9	0.395	137.7	
14.0	0.753	69.4	1.405	-98.6	0.132	-54.5	0.343	122.3	
15.0	0.737	57.8	1.342	-117.8	0.156	-69.8	0.382	92.6	
16.0	0.718	45.9	1.274	-136.3	0.187	-84.3	0.411	75.2	
17.0	0.722	34.0	1.245	-152.8	0.232	-98.1	0.356	68.9	
18.0	0.703	22.0	1.211	-171.5	0.295	-114.7	0.310	53.3	
19.0	0.657	10.6	1.164	168.6	0.379	-134.5	0.319	39.7	
20.0	0.717	-1.0	1.174	147.8	0.514	-158.6	0.270	39.6	

# EFA160A

## DATA SHEET

### Low Distortion GaAs Power FET

- +29.0dBm TYPICAL OUTPUT POWER
- 9.0dB TYPICAL POWER GAIN AT 12GHz
- 0.3 X 1600 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 30mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
P <sub>1dB</sub>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f=12GHz 27.0	f=12GHz 29.0	f=18GHz 29.0	dBm
G <sub>1dB</sub>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f=12GHz 7.0	f=12GHz 9.0	f=18GHz 6.5	dB
PAE	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f=12GHz	34		%
I <sub>dss</sub>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	260	420	600	mA
G <sub>m</sub>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	180	240		mS
V <sub>p</sub>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =4.0mA		-2.0	-3.5	V
BV <sub>gd</sub>	Drain Breakdown Voltage I <sub>gd</sub> =1.6mA	-12	-15		V
BV <sub>gs</sub>	Source Breakdown Voltage I <sub>gs</sub> =1.6mA	-7	-14		V
R <sub>th</sub>	Thermal Resistance (Au-Sn Eutectic Attach)		30		°C/W

### MAXIMUM RATINGS AT 25 °C

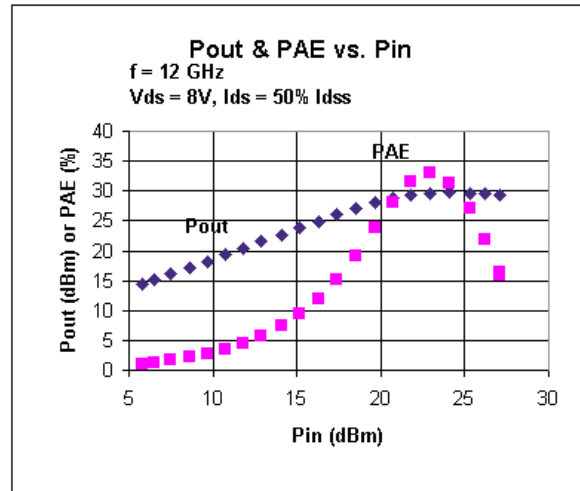
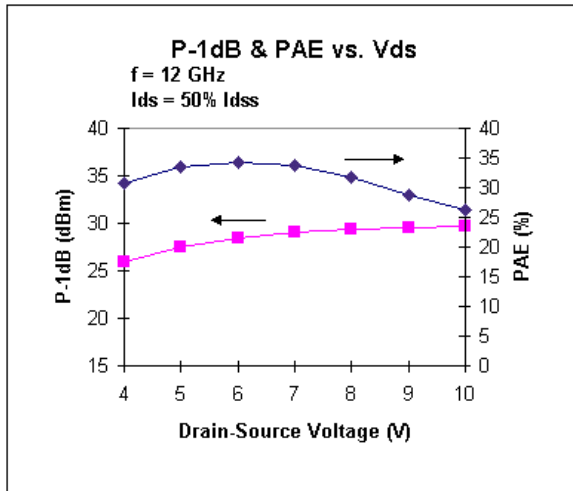
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-4V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	475mA
I <sub>gsf</sub>	Forward Gate Current	40mA	7mA
P <sub>in</sub>	Input Power	28dBm	@ 3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	4.5W	3.8W



# EFA160A

## DATA SHEET

### Low Distortion GaAs Power FET



### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.936	-81.9	9.025	133.3	0.035	48.7	0.221	-106.2
2.0	0.911	-119.8	5.964	108.8	0.047	27.7	0.285	-132.0
3.0	0.903	-138.7	4.275	94.5	0.050	18.4	0.319	-141.6
4.0	0.903	-149.8	3.297	84.3	0.050	13.0	0.347	-145.0
5.0	0.900	-157.8	2.644	75.5	0.049	9.3	0.382	-147.5
6.0	0.903	-162.4	2.207	68.6	0.048	6.4	0.413	-148.0
7.0	0.905	-165.8	1.884	62.3	0.047	5.6	0.445	-148.7
8.0	0.908	-168.0	1.640	56.4	0.046	3.6	0.476	-149.5
9.0	0.913	-170.0	1.451	51.2	0.044	3.1	0.510	-150.4
10.0	0.914	-171.8	1.297	46.2	0.042	3.9	0.536	-151.0
11.0	0.918	-173.7	1.172	41.0	0.041	3.2	0.563	-152.2
12.0	0.920	-175.2	1.067	36.1	0.039	2.6	0.592	-153.8
13.0	0.924	-177.4	0.977	31.0	0.038	2.9	0.612	-155.2
14.0	0.925	-179.9	0.901	25.9	0.038	1.8	0.635	-157.2
15.0	0.925	177.5	0.836	20.8	0.038	1.6	0.653	-159.4
16.0	0.929	174.2	0.775	15.4	0.038	0.7	0.675	-161.8
17.0	0.927	171.0	0.721	10.0	0.037	1.5	0.688	-164.7
18.0	0.928	167.6	0.670	4.6	0.037	2.2	0.706	-167.7
19.0	0.927	164.8	0.626	-0.6	0.037	1.4	0.721	-171.1
20.0	0.931	162.1	0.580	-5.4	0.037	1.0	0.738	-174.6
21.0	0.945	162.3	0.502	-9.7	0.036	2.4	0.771	-178.4
22.0	0.951	161.1	0.469	-13.0	0.033	2.9	0.786	178.6
23.0	0.960	159.9	0.433	-16.9	0.035	5.0	0.803	176.2
24.0	0.961	159.6	0.409	-20.1	0.037	8.9	0.821	174.3
25.0	0.973	159.3	0.391	-22.7	0.037	10.9	0.831	172.5
26.0	0.969	159.6	0.368	-24.8	0.039	10.8	0.849	170.6

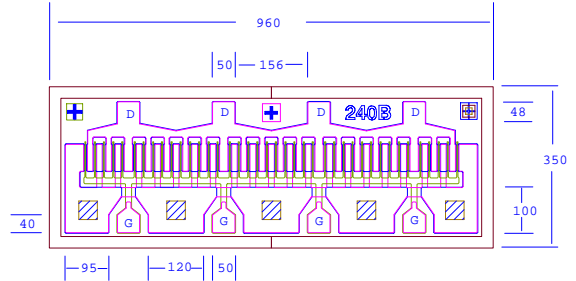
Note: The data included 0.7 mils diameter Au bonding wires:  
 4 gate wires, 15 mils each; 4 drain wires, 20 mils each; 10 source wires, 7 mils each.

# EFA240B/EFA240BV

## DATA SHEET

### Low Distortion GaAs Power FET

- +31.0dBm TYPICAL OUTPUT POWER
- 8.5dB TYPICAL POWER GAIN FOR EFA240B AND 10.5dB FOR EFA240BV AT 12GHz
- 0.3 X 2400 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- EFA240BV WITH VIA HOLE SOURCE GROUNDING
- Idss SORTED IN 40mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EFA240B			EFA240BV			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	29.0	31.0		29.0	31.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	7.0	8.5 6.0		9.0	10.5 8.0		dB
<b>PAE</b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>		33			35		%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	400	680	880	400	680	880	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	280	360		280	360		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6 mA		-2.0	-3.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-12	-15		-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-7	-14		-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		20			15		°C/W

### MAXIMUM RATINGS AT 25 °C

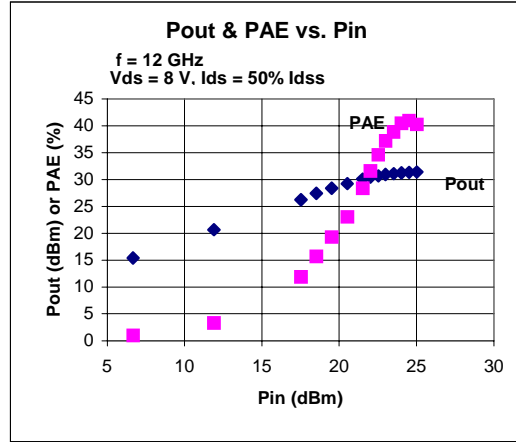
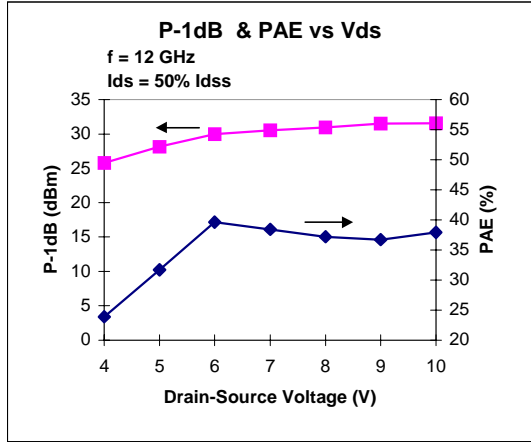
SYMBOLS	PARAMETERS	EFA240B		EFA240BV	
		ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	710mA	I <sub>ds</sub>	I <sub>ds</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	60mA	10mA	60mA	10mA
<b>P<sub>in</sub></b>	Input Power	29dBm	@ 3dB Compression	29dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	6.8W	5.7W	9.1W	7.6W

# EFA240B/EFA240BV

## DATA SHEET

### Low Distortion GaAs Power FET

EFA240B



### S-PARAMETERS

EFA240B 8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.924	-109.6	8.554	117.9	0.035	34.7	0.345	-151.2
2.0	0.910	-140.4	4.879	97.0	0.039	20.8	0.407	-161.6
4.0	0.905	-157.4	2.561	77.8	0.039	14.8	0.447	-166.5
6.0	0.904	-163.9	1.717	64.0	0.037	16.1	0.492	-165.7
8.0	0.907	-168.2	1.295	52.5	0.036	17.7	0.541	-163.7
10.0	0.909	-171.9	1.020	42.7	0.032	22.5	0.594	-162.2
12.0	0.917	-177.5	0.835	32.1	0.031	24.8	0.653	-162.4
14.0	0.924	-179.1	0.688	22.4	0.030	25.9	0.706	-165.7
16.0	0.927	-174.9	0.569	11.6	0.032	23.2	0.741	-171.9
18.0	0.944	-174.3	0.474	2.4	0.033	22.4	0.778	-179.5
20.0	0.953	-173.2	0.395	-7.7	0.035	24.0	0.813	-171.7
22.0	0.942	-175.2	0.326	-13.6	0.040	24.7	0.830	-164.7
24.0	0.960	-177.3	0.290	-17.6	0.044	30.3	0.848	-160.2
26.0	0.951	-177.1	0.257	-19.2	0.053	39.2	0.846	-160.0

EFA240BV 8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.907	-109.0	9.976	119.2	0.033	33.9	0.356	-145.6
2.0	0.905	-142.3	5.784	97.9	0.038	17.7	0.425	-157.1
4.0	0.907	-163.3	2.990	77.1	0.038	5.5	0.471	-161.2
6.0	0.915	-171.5	1.961	63.2	0.035	1.4	0.520	-161.0
8.0	0.923	-175.8	1.431	51.7	0.032	-1.2	0.574	-161.2
10.0	0.933	-178.0	1.106	41.8	0.029	-2.4	0.627	-162.0
12.0	0.940	-180.0	0.887	32.4	0.027	-3.0	0.677	-163.9
14.0	0.941	-177.8	0.731	23.3	0.025	-5.5	0.721	-166.5
16.0	0.947	-175.1	0.616	14.1	0.024	-8.8	0.756	-169.8
18.0	0.949	-171.5	0.531	4.7	0.025	-11.9	0.791	-173.7
20.0	0.954	-167.9	0.459	-4.5	0.024	-13.0	0.818	-177.9
22.0	0.967	-167.2	0.389	-12.4	0.023	-12.5	0.848	-175.9
24.0	0.970	-165.3	0.335	-19.6	0.024	-11.2	0.873	-172.2
26.0	0.971	-163.3	0.292	-25.8	0.024	-0.7	0.900	-170.7

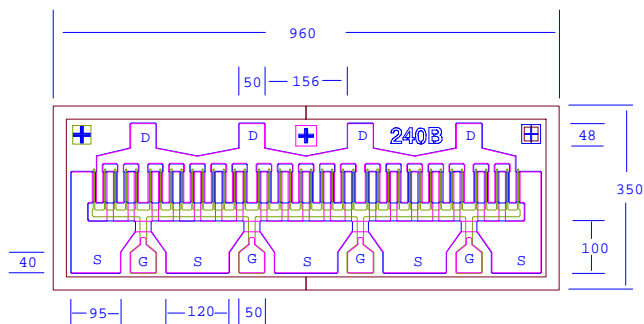
Note: The data included 0.7 mils diameter Au bonding wires; 4 gate wires, 15 mils each; 4 drain wires, 20 mils each; 10 source wires, 7 mils each; no source wires for EFA240BV.

# EFC240B

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

- +31.0dBm TYPICAL OUTPUT POWER
- 8.5dB TYPICAL POWER GAIN AT 12GHz
- HIGH BV<sub>gd</sub> FOR 10V BIAS
- 0.3 X 2400 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Id<sub>ss</sub> SORTED IN 40mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f=12GHz f=18GHz	29.0	31.0 31.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f=12GHz f=18GHz	7.0	8.5 6.0		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f=12GHz		33		%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	320	520	720	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	200	280		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6mA		-2.5	-4.0	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-15	-20		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-10	-17		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		20		°C/W

### MAXIMUM RATINGS AT 25 °C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	14V	10V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4.5V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	570mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	60mA	10mA
<b>P<sub>in</sub></b>	Input Power	29dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	6.8 W	5.7 W

# EFC240B

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

10V, 1/2 Idss

Freq	S11	S11	S21	S21	S12	S12	S22	S22
GHz	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang
1.000	0.944	-86.7	7.064	130.8	0.041	41.9	0.296	-132.9
2.000	0.915	-125.9	4.551	104.6	0.052	22.7	0.374	-146.8
3.000	0.907	-144.8	3.217	89.3	0.055	13.2	0.409	-152.2
4.000	0.907	-155.6	2.450	78.1	0.054	6.7	0.433	-154.1
5.000	0.912	-161.6	1.929	69.0	0.052	2.7	0.460	-157.6
6.000	0.911	-166.1	1.596	60.9	0.050	0.1	0.487	-158.3
7.000	0.920	-169.0	1.362	54.1	0.049	-2.2	0.512	-159.2
8.000	0.915	-171.1	1.181	47.7	0.047	-3.4	0.549	-161.0
9.000	0.919	-173.3	1.040	41.7	0.045	-4.5	0.586	-161.9
10.000	0.922	-176.1	0.922	35.7	0.041	-5.2	0.620	-162.0
11.000	0.925	-179.2	0.826	30.0	0.041	-6.2	0.647	-162.2
12.000	0.932	178.8	0.747	24.7	0.039	-7.5	0.673	-163.2
13.000	0.933	177.0	0.681	19.1	0.037	-7.5	0.690	-165.6
14.000	0.939	175.4	0.622	13.8	0.035	-7.7	0.716	-168.5
15.000	0.941	172.9	0.569	8.5	0.035	-7.0	0.739	-170.1
16.000	0.945	170.6	0.522	3.0	0.035	-6.4	0.752	-172.8
17.000	0.946	169.7	0.483	-2.1	0.035	-7.5	0.764	-177.3
18.000	0.952	170.3	0.452	-7.0	0.034	-6.2	0.776	176.4
19.000	0.955	170.4	0.421	-12.7	0.034	-6.5	0.791	169.8
20.000	0.955	168.7	0.387	-18.0	0.035	-3.8	0.813	164.9
21.000	0.954	160.5	0.359	-23.1	0.034	-5.3	0.835	168.3
22.000	0.948	158.1	0.327	-26.7	0.035	-2.1	0.847	166.2
23.000	0.958	157.0	0.303	-30.7	0.035	0.6	0.870	163.7
24.000	0.956	156.1	0.275	-33.9	0.036	2.9	0.876	162.1
25.000	0.961	155.3	0.251	-36.4	0.038	7.7	0.887	160.5
26.000	0.954	153.5	0.232	-39.0	0.036	10.4	0.897	160.1

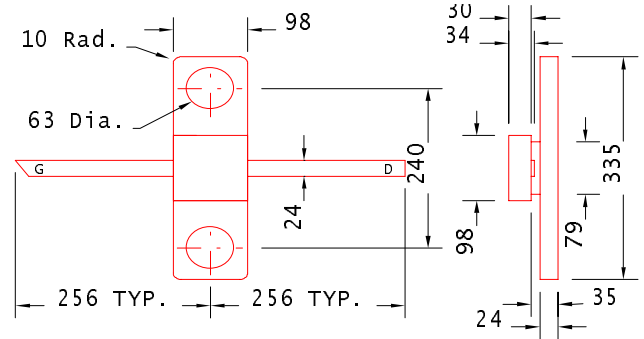
Note: The data included 0.7 mils diameter Au bonding wires:  
4 gate wires, 15 mils each; 4 drain wires, 20 mils each; 10 source wires, 7 mils each.

# EFA240B-100F

## DATA SHEET

### Low Distortion GaAs Power FET

- HERMETIC 100mil CERAMIC FLANGE PACKAGE
- +31.0dBm TYPICAL OUTPUT POWER
- 7.0dB TYPICAL POWER GAIN AT 8GHz
- 0.3 X 2400 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
P <sub>1dB</sub>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub> f=8GHz	29.0	31.0		dBm
G <sub>1dB</sub>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub> f=8GHz	5.5	7.0		dB
PAE	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub> f=8GHz		30		%
I <sub>dss</sub>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	400	680	880	mA
G <sub>m</sub>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	280	360		mS
V <sub>p</sub>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6mA		-2.0	-3.5	V
BV <sub>gd</sub>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-12	-15		V
BV <sub>gs</sub>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-7	-14		V
R <sub>th</sub>	Thermal Resistance		22*		°C/W

\* Overall R<sub>th</sub> depends on case mounting.

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-4V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	650mA
I <sub>gsf</sub>	Forward Gate Current	60mA	10mA
P <sub>in</sub>	Input Power	29dBm	@ 3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	6.3W	5.2W

# EFA240B-100F

## DATA SHEET

### Low Distortion GaAs Power FET

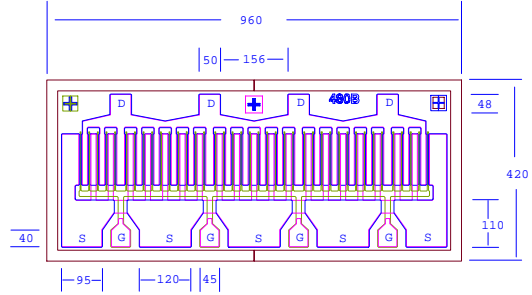
S-PARAMETERS								
8V, 1/2 Idss								
FREQ	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1.0	0.892	-116.0	8.585	112.8	0.035	37.1	0.343	-151.4
2.0	0.850	-150.3	5.034	85.3	0.044	30.1	0.371	-166.1
3.0	0.830	-166.5	3.583	67.0	0.051	27.2	0.374	-175.0
4.0	0.820	177.1	2.830	50.2	0.059	24.6	0.383	179.7
5.0	0.814	161.1	2.351	33.3	0.067	18.6	0.377	172.0
6.0	0.807	151.3	2.008	17.5	0.076	12.5	0.386	155.1
7.0	0.804	140.8	1.731	2.5	0.083	6.0	0.412	142.0
8.0	0.803	131.3	1.511	-11.2	0.090	0.1	0.444	131.6
9.0	0.810	116.1	1.323	-25.5	0.098	-8.2	0.442	127.9
10.0	0.819	106.6	1.185	-39.0	0.107	-16.2	0.445	118.1
11.0	0.803	103.8	1.128	-51.9	0.123	-24.7	0.488	102.8
12.0	0.764	96.4	1.098	-65.2	0.143	-33.9	0.513	95.6
13.0	0.742	79.4	1.039	-80.0	0.162	-45.3	0.485	92.7
14.0	0.732	64.6	0.984	-94.4	0.185	-57.2	0.446	81.8
15.0	0.708	53.5	0.954	-111.1	0.215	-71.9	0.473	65.9
16.0	0.674	42.7	0.925	-127.4	0.251	-86.5	0.457	55.4
17.0	0.669	33.2	0.940	-142.9	0.309	-101.4	0.362	50.0
18.0	0.626	23.6	0.938	-161.1	0.377	-119.7	0.291	39.9
19.0	0.534	16.7	0.932	179.6	0.461	-141.3	0.303	41.3
20.0	0.540	12.3	0.959	158.9	0.583	-166.7	0.347	53.1

# EFA480B

## DATA SHEET

### Low Distortion GaAs Power FET

- +34.0dBm TYPICAL OUTPUT POWER
- 10.0dB TYPICAL POWER GAIN AT 8GHz
- 0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 80mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression		34.0		dBm	
	V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f = 8GHz	32.0	34.0		
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression		10.0		dB	
	V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f = 8GHz	4.0	6.0		
<b>PAE</b>	Gain at 1dB Compression		35		%	
<b>I<sub>dss</sub></b>	Saturated Drain Current	V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	800	1360	1760	mA
<b>G<sub>m</sub></b>	Transconductance	V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	560	720		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage	V <sub>ds</sub> =3V, I <sub>ds</sub> =10mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage	I <sub>gd</sub> =4.8mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage	I <sub>gs</sub> =4.8mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		10			°C/W

### MAXIMUM RATINGS AT 25 °C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	1.4A
<b>I<sub>gsf</sub></b>	Forward Gate Current	120mA	20mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	14 W	11 W



# EFA480B

## DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.944	-115.5	11.585	117.1	0.019	33.5	0.384	-159.9
1.000	0.929	-145.4	6.478	98.5	0.021	21.3	0.425	-165.4
1.500	0.926	-157.1	4.413	88.9	0.021	18.2	0.440	-166.5
2.000	0.925	-163.3	3.326	81.9	0.021	17.7	0.453	-166.2
2.500	0.925	-167.2	2.659	76.0	0.021	18.5	0.465	-165.6
3.000	0.925	-169.9	2.208	70.8	0.021	20.0	0.479	-164.8
3.500	0.925	-171.9	1.883	65.9	0.021	22.0	0.494	-164.1
4.000	0.926	-173.6	1.636	61.3	0.021	24.4	0.510	-163.6
4.500	0.927	-174.9	1.443	57.0	0.022	27.0	0.526	-163.2
5.000	0.928	-176.1	1.287	52.7	0.022	29.8	0.543	-162.9
5.500	0.928	-177.1	1.158	48.6	0.022	32.8	0.561	-162.9
6.000	0.929	-178.0	1.050	44.7	0.022	35.9	0.579	-162.9
6.500	0.930	-178.9	0.958	40.8	0.023	39.0	0.596	-163.1
7.000	0.931	-179.7	0.878	37.1	0.023	42.0	0.613	-163.5
7.500	0.932	-179.6	0.809	33.5	0.024	45.0	0.630	-163.9
8.000	0.933	-178.9	0.747	30.0	0.025	47.8	0.647	-164.5
8.500	0.934	-178.3	0.693	26.6	0.026	50.4	0.663	-165.1
9.000	0.935	-177.6	0.644	23.4	0.027	52.9	0.679	-165.7
9.500	0.936	-177.0	0.600	20.2	0.028	55.1	0.694	-166.5
10.000	0.937	-176.4	0.561	17.1	0.030	57.1	0.708	-167.3

Note: The data included 0.7 mils diameter Au bonding wires:  
4 gate wires, 20 mils each; 4 drain wires, 12 mils each; 10 source wires, 7 mils each.

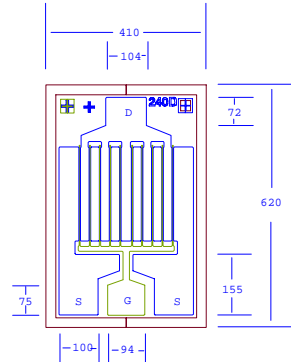
# EFA240D

DATA SHEET

Rev.1

## Low Distortion GaAs Power FET

- +31.0dBm TYPICAL OUTPUT POWER
- 18.5dB TYPICAL POWER GAIN AT 2GHz
- 0.5 X 2400 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 40mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f= 2GHz 29.0	f= 4GHz 31.0 31.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f= 2GHz 16.0	f= 4GHz 18.5 13.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>		f=2GHz 45		%
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	400	680	880	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	280	360		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		23		°C/W

### MAXIMUM RATINGS AT 25 °C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	620mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	60mA	10mA
<b>P<sub>in</sub></b>	Input Power	29dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	6.0 W	5.0 W

# EFA240D

## DATA SHEET

Rev.1

### Low Distortion GaAs Power FET

#### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.950	-75.6	11.303	136.8	0.027	53.1	0.195	-119.8
1.000	0.906	-116.5	7.670	113.0	0.036	35.5	0.264	-142.3
1.500	0.888	-138.2	5.566	99.1	0.040	27.9	0.290	-152.3
2.000	0.880	-151.5	4.317	89.4	0.041	24.4	0.303	-157.5
2.500	0.877	-160.7	3.510	81.6	0.042	22.9	0.312	-160.6
3.000	0.875	-167.7	2.952	74.9	0.043	22.5	0.321	-162.6
3.500	0.875	-173.3	2.544	68.8	0.043	22.6	0.329	-164.0
4.000	0.876	-178.1	2.233	63.2	0.044	23.2	0.338	-165.0
4.500	0.877	177.7	1.989	57.8	0.045	24.1	0.347	-165.9
5.000	0.879	173.9	1.792	52.7	0.046	25.1	0.356	-166.7
5.500	0.881	170.4	1.630	47.8	0.046	26.3	0.366	-167.5
6.000	0.883	167.1	1.493	43.0	0.047	27.5	0.377	-168.3
6.500	0.885	164.1	1.377	38.3	0.048	28.7	0.389	-169.1
7.000	0.887	161.1	1.276	33.7	0.050	30.0	0.400	-169.9
7.500	0.890	158.4	1.188	29.2	0.051	31.2	0.413	-170.8
8.000	0.893	155.7	1.109	24.8	0.052	32.3	0.426	-171.8
8.500	0.896	153.1	1.040	20.5	0.054	33.4	0.439	-172.9
9.000	0.899	150.6	0.977	16.2	0.056	34.4	0.453	-174.0
9.500	0.902	148.1	0.920	12.1	0.058	35.3	0.467	-175.2
10.000	0.905	145.7	0.867	8.0	0.060	36.0	0.481	-176.5

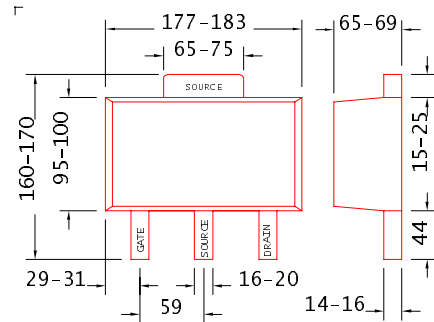
Note: The data included 0.7 mils diameter Au bonding wires:  
1 gate wires, 20 mils each; 1 drain wires, 12 mils each; 4 source wires, 7 mils each.

# EFA240D-SOT89

## DATA SHEET DC-4GHz Low Distortion GaAs Power FET

### Features

- LOW COST SURFACE-MOUNT PLASTIC PACKAGE
- +31.0dBm TYPICAL OUTPUT POWER
- 13.0dB TYPICAL POWER GAIN AT 2GHz
- 0.7dB TYPICAL NOISE FIGURE AT 2GHz
- +48dBm TYPICAL OUTPUT 3rd ORDER INTERCEPT POINT AT 2GHz
- 0.5 X 2400 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY



### Applications

- Analog and Digital Wireless System
- HPA

### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
P <sub>1dB</sub>	Output Power at 1dB Compression f = 2GHz V <sub>ds</sub> =7V, I <sub>ds</sub> =350mA	29.5	31.0		dBm
G <sub>1dB</sub>	Gain at 1dB Compression f = 2GHz V <sub>ds</sub> =7V, I <sub>ds</sub> =350mA	11.0	13.0		dB
PAE	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =7V, I <sub>ds</sub> =350mA f = 2GHz		45		%
NF	Noise Figure f = 2GHz V <sub>ds</sub> =5V, I <sub>ds</sub> =150mA V <sub>ds</sub> =5-7V, I <sub>ds</sub> =350mA		0.7 1.2		dB
IP3	Output 3rd Order Intercept Point f = 2GHz V <sub>ds</sub> =5-7V, I <sub>ds</sub> =350mA V <sub>ds</sub> =5V, I <sub>ds</sub> =150mA		48 36		dBm
I <sub>dss</sub>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	440	680	880	mA
G <sub>m</sub>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	280	360		mS
V <sub>p</sub>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6mA		-2.0	-3.5	V
BV <sub>gd</sub>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-11	-15		V
BV <sub>gs</sub>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-7	-14		V
R <sub>th</sub>	Thermal Resistance		25*		°C/W

\*Overall R<sub>th</sub> depends on case mounting.

### MAXIMUM RATINGS AT 25°C

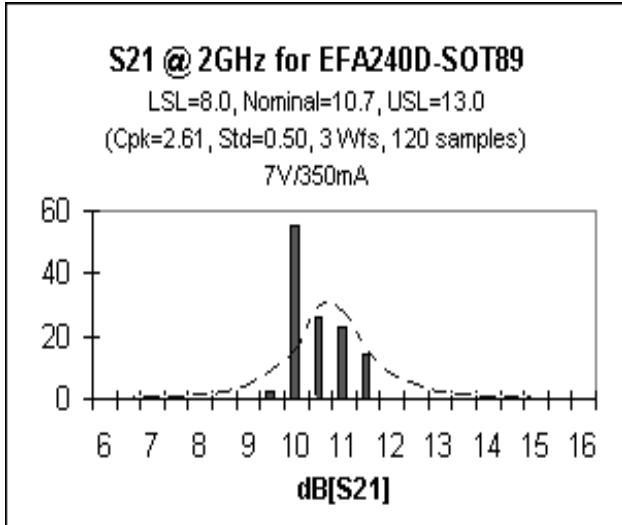
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	7V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-4V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	660mA
I <sub>gsf</sub>	Forward Gate Current	60mA	10mA
P <sub>in</sub>	Input Power	29dBm	@ 3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	5.5 W	4.6 W

# EFA240D-SOT89

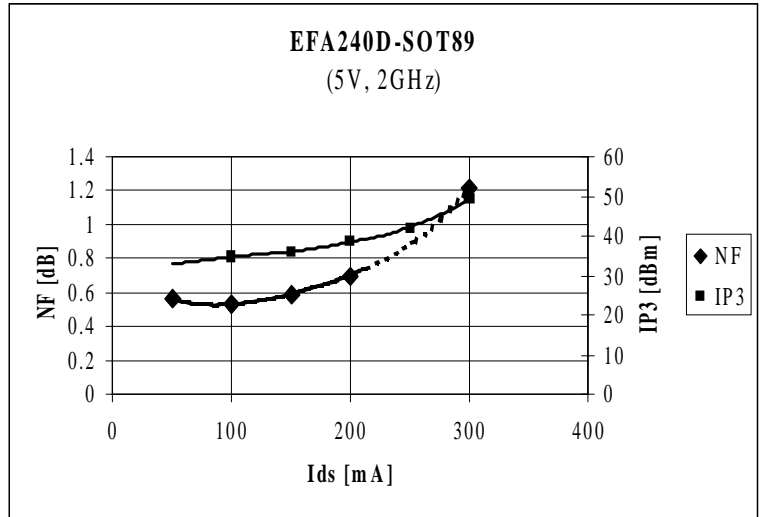
## DATA SHEET DC-4GHz Low Distortion GaAs Power FET

### Typical Performance

S21 Distribution



Noise Figure & IP3



### S-PARAMETERS

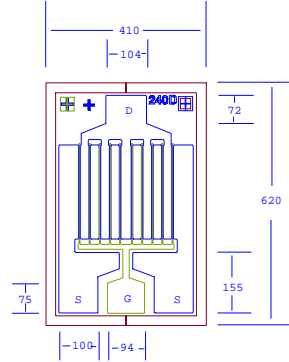
5V, 150mA										7V, 350mA									
FREQ	S11		S21		S12		S22			FREQ	S11		S21		S12		S22		
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG		(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG	
0.1	0.980	-29.5	15.580	162.1	0.009	50.3	0.273	-165.8		0.1	0.970	-32.8	17.023	161.5	0.019	75.7	0.148	-137.8	
0.2	0.964	-56.5	14.250	147.1	0.024	61.6	0.348	-155.7		0.2	0.952	-58.4	15.321	145.4	0.023	58.2	0.241	-133.9	
0.3	0.942	-78.3	12.624	134.2	0.029	51.8	0.407	-157.6		0.3	0.927	-80.6	13.396	132.4	0.030	49.9	0.312	-140.8	
0.4	0.923	-96.1	11.069	123.8	0.035	43.6	0.459	-161.2		0.4	0.911	-98.4	11.673	121.9	0.034	41.9	0.362	-147.9	
0.5	0.907	-110.1	9.717	115.0	0.039	38.2	0.494	-165.6		0.5	0.896	-112.	10.188	113.2	0.039	36.0	0.395	-154.6	
1.0	0.870	-152.5	5.742	86.6	0.048	23.1	0.547	-179.8		1.0	0.861	-154.0	5.962	84.6	0.047	19.8	0.442	-171.7	
1.5	0.765	-170.0	4.782	72.1	0.064	19.6	0.439	166.2		1.5	0.760	-171.3	4.853	70.1	0.060	16.8	0.319	177.2	
2.0	0.750	169.6	3.721	55.6	0.072	13.1	0.445	154.7		2.0	0.748	168.6	3.767	53.3	0.066	10.5	0.326	165.5	
2.5	0.735	152.7	3.092	40.9	0.080	6.1	0.435	144.6		2.5	0.735	152.1	3.119	38.2	0.072	4.7	0.318	156.6	
3.0	0.723	137.1	2.697	26.0	0.090	-1.9	0.420	133.7		3.0	0.724	136.7	2.707	23.3	0.080	-1.6	0.303	147.2	
3.5	0.722	119.8	2.411	10.4	0.101	-10.8	0.399	120.3		3.5	0.725	119.5	2.413	7.7	0.089	-9.6	0.281	135.1	
4.0	0.721	101.3	2.140	-6.9	0.110	-22.6	0.401	101.6		4.0	0.724	101.0	2.147	-9.5	0.096	-19.9	0.274	115.1	
4.5	0.744	82.8	1.849	-23.5	0.113	-33.8	0.433	81.3		4.5	0.746	82.6	1.863	-26.3	0.100	-30.0	0.299	91.3	
5.0	0.781	66.2	1.577	-38.8	0.113	-45.0	0.495	65.4		5.0	0.785	66.1	1.605	-42.2	0.102	-40.0	0.364	73.1	
5.5	0.812	52.3	1.353	-52.7	0.110	-55.3	0.550	54.0		5.5	0.817	52.3	1.388	-56.5	0.102	-49.7	0.428	61.2	
6.0	0.830	40.0	1.174	-65.7	0.109	-64.7	0.582	44.3		6.0	0.835	40.0	1.206	-70.0	0.102	-59.0	0.471	51.4	

# EFC240D

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

- +31.0dBm TYPICAL OUTPUT POWER
- 18.5dB TYPICAL POWER GAIN AT 2GHz
- HIGH BV<sub>gd</sub> FOR 10V BIAS
- 0.5 X 2400 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Id<sub>ss</sub> SORTED IN 40mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f= 2GHz f= 4 GHz	29.0	31.0 31.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f= 2GHz f= 4GHz	16.0	18.5 13.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =10V, I <sub>ds</sub> =50% I <sub>ds</sub> f=2GHz		45		%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	320	480	720	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	200	280		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =6mA		-2.5	-4.0	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =2.4mA	-15	-20		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =2.4mA	-10	-17		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		23		°C/W

### MAXIMUM RATINGS AT 25 °C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	14V	10V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4.5V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	500mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	60mA	10mA
<b>P<sub>in</sub></b>	Input Power	29dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	6.0W	5.0W

# EFC240D

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

10V, 1/2 Idss

Freq GHz	S11 Mag	S11 Ang	S21 Mag	S21 Ang	S12 Mag	S12 Ang	S22 Mag	S22 Ang
0.500	0.962	-66.3	11.912	141.2	0.025	55.9	0.239	-129.1
1.000	0.933	-106.1	8.577	117.9	0.036	36.9	0.337	-144.0
1.500	0.859	-121.0	6.591	108.2	0.042	32.6	0.303	-146.3
2.000	0.860	-136.6	5.272	97.9	0.044	26.7	0.330	-151.9
2.500	0.849	-147.5	4.344	89.7	0.046	22.6	0.343	-155.1
3.000	0.848	-155.8	3.689	82.9	0.047	20.8	0.354	-157.6
3.500	0.846	-162.2	3.195	76.9	0.047	19.4	0.365	-159.4
4.000	0.846	-167.3	2.809	71.5	0.048	18.7	0.373	-160.6
4.500	0.849	-172.0	2.472	66.5	0.047	18.7	0.389	-162.9
5.000	0.856	-176.1	2.229	61.8	0.048	18.6	0.399	-163.5
5.500	0.853	-179.3	2.024	57.2	0.048	18.8	0.411	-164.5
6.000	0.855	177.4	1.852	52.9	0.048	20.4	0.422	-165.6
6.500	0.857	174.4	1.708	48.7	0.048	19.7	0.434	-165.8
7.000	0.861	171.7	1.577	44.8	0.049	20.7	0.444	-166.5
7.500	0.861	169.3	1.466	41.0	0.049	20.7	0.457	-167.7
8.000	0.865	167.0	1.375	37.2	0.049	21.7	0.468	-168.4
8.500	0.869	165.2	1.288	33.7	0.050	22.1	0.477	-169.7
9.000	0.873	163.5	1.213	30.1	0.050	24.0	0.487	-171.2
9.500	0.877	161.9	1.146	26.8	0.052	24.7	0.500	-172.4
10.000	0.876	160.4	1.085	23.3	0.053	25.4	0.509	-174.2

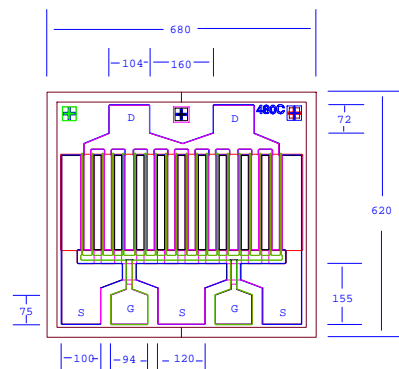
Note: The data included 0.7 mils diameter Au bonding wires:  
1 gate wires, 20 mils each; 2 drain wires, 12 mils each; 4 source wires, 7 mils each.

# EFA480C

## DATA SHEET

### Low Distortion GaAs Power FET

- **+34.0dBm TYPICAL OUTPUT POWER**
- **18.0dB TYPICAL POWER GAIN AT 2GHz**
- **0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE**
- **Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK**
- **ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY**
- **Idss SORTED IN 80mA PER BIN RANGE**



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	32.0	34.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	f= 2GHz	18.0		dB
		f= 4GHz	12.5		
<b>PAE</b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>		40		%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	800	1360	1760	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	560	720		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =10mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =4.8mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		12		°C/W

### MAXIMUM RATINGS AT 25 °C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	1.2A
<b>I<sub>gsf</sub></b>	Forward Gate Current	120mA	20mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	11.4 W	9.5 W



# EFA480C

## DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.944	-119.8	9.669	115.5	0.023	33.8	0.515	-166.9
1.000	0.931	-149.2	5.352	97.6	0.026	24.2	0.553	-172.1
1.500	0.928	-161.0	3.646	88.3	0.027	23.1	0.564	-174.0
2.000	0.927	-167.6	2.756	81.6	0.027	24.4	0.569	-175.0
2.500	0.927	-172.0	2.213	75.9	0.028	26.6	0.574	-175.4
3.000	0.927	-175.4	1.849	70.7	0.029	29.2	0.580	-175.7
3.500	0.928	-178.1	1.587	66.0	0.030	31.9	0.585	-175.9
4.000	0.928	179.6	1.389	61.4	0.031	34.6	0.591	-176.0
4.500	0.929	177.5	1.235	57.0	0.032	37.2	0.597	-176.1
5.000	0.930	175.6	1.112	52.8	0.034	39.6	0.604	-176.3
5.500	0.931	173.9	1.010	48.7	0.035	41.9	0.612	-176.5
6.000	0.932	172.3	0.925	44.7	0.037	44.1	0.620	-176.7
6.500	0.933	170.7	0.853	40.8	0.039	46.0	0.628	-176.9
7.000	0.934	169.2	0.790	37.0	0.040	47.8	0.636	-177.2
7.500	0.935	167.7	0.735	33.3	0.042	49.4	0.645	-177.5
8.000	0.937	166.3	0.687	29.7	0.044	50.8	0.654	-177.9
8.500	0.938	164.9	0.643	26.2	0.047	52.1	0.664	-178.3
9.000	0.939	163.6	0.604	22.8	0.049	53.2	0.673	-178.8
9.500	0.941	162.3	0.569	19.5	0.051	54.1	0.683	-179.4
10.000	0.942	160.9	0.537	16.2	0.054	54.9	0.693	-179.9

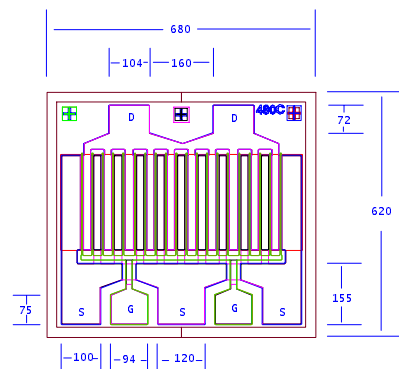
Note: The data included 0.7 mils diameter Au bonding wires:  
2 gate wires, 20 mils each; 2 drain wires, 12 mils each; 6 source wires, 7 mils each.

# EFC480C

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

- +33.5dBm TYPICAL OUTPUT POWER
- 18.0dB TYPICAL POWER GAIN AT 2GHz
- High BV<sub>gd</sub> FOR 10V BIAS
- 0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Id<sub>ss</sub> SORTED IN 80mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	f= 2GHz 32.0	f= 2GHz 33.5		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	f= 2GHz 16.0	f= 2GHz 18.0		dB
<b>PAE</b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>ds</sub>	f= 2GHz 40			%
<b>I<sub>ds</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	640	960	1440	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	200	560		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =10mA		-2.5	-4.0	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-15	-20		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =4.8mA	-10	-17		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		12		°C/W

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	14V	10V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4.5V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>ds</sub>	960mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	120mA	20mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	11.4 W	9.5 W

# EFC480C

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

S-PARAMETERS									
10V, 1/2 Idss									
Freq GHz	---S11---		---S21---		---S12---		---S22---		
	Mag	Ang	Mag	Ang	Mag	Ang	Mag	Ang	
0.500	0.937	-106.2	10.161	120.8	0.022	35.8	0.518	-166.8	
1.000	0.897	-134.9	6.389	104.7	0.028	26.4	0.505	-168.3	
1.500	0.897	-151.8	4.443	93.5	0.028	21.5	0.524	-171.2	
2.000	0.897	-161.0	3.370	85.4	0.029	19.0	0.533	-173.0	
2.500	0.898	-167.2	2.695	79.2	0.030	20.2	0.539	-173.8	
3.000	0.895	-171.8	2.231	73.9	0.030	19.5	0.542	-174.2	
3.500	0.890	-175.4	1.894	69.4	0.030	20.9	0.542	-173.9	
4.000	0.850	-176.6	1.654	66.9	0.026	27.6	0.560	-172.2	
4.500	0.901	177.7	1.535	59.9	0.032	23.1	0.607	-169.5	
5.000	0.899	174.5	1.357	55.2	0.031	25.8	0.617	-170.8	
5.500	0.900	172.5	1.208	51.4	0.031	28.1	0.620	-171.8	
6.000	0.901	170.8	1.087	48.2	0.031	30.4	0.619	-172.8	
6.500	0.902	169.6	0.999	45.8	0.032	32.0	0.616	-172.6	
7.000	0.893	168.8	0.941	43.3	0.033	37.1	0.637	-171.2	
7.500	0.904	170.7	0.916	39.2	0.037	34.8	0.669	-172.8	
8.000	0.919	169.5	0.840	34.2	0.036	35.0	0.681	-175.0	
8.500	0.918	169.2	0.783	31.0	0.038	36.6	0.693	-176.9	
9.000	0.924	168.7	0.729	27.9	0.037	37.6	0.701	-178.6	
9.500	0.927	168.0	0.687	24.5	0.038	39.8	0.706	-179.3	
10.000	0.932	167.3	0.647	22.3	0.040	42.4	0.716	179.8	

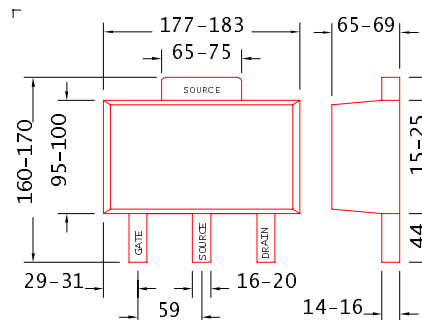
Note: The data included 0.7 mils diameter Au bonding wires:  
2 gate wires, 20 mils each; 2 drain wires, 12 mils each; 6 source wires, 7 mils each.

# EFA480C-SOT89

## DATA SHEET DC-4GHz Low Distortion GaAs Power FET

### Features

- **LOW COST SURFACE-MOUNT PLASTIC PACKAGE**
- **+34.0dBm TYPICAL OUTPUT POWER**
- **12.0dB TYPICAL POWER GAIN AT 2GHz**
- **0.8dB TYPICAL NOISE FIGURE AT 2GHz**
- **+48dBm TYPICAL OUTPUT 3rd ORDER INTERCEPT POINT AT 2GHz**
- **0.5 X 4800 MICRON RECESSED “MUSHROOM” GATE**
- **Si<sub>3</sub>N<sub>4</sub> PASSIVATION**
- **ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY**



### Applications

- **Analog and Digital Wireless System**
- **HPA**

### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f = 2GHz V <sub>ds</sub> =7V, I <sub>ds</sub> =750mA	32.5	34.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f = 2GHz V <sub>ds</sub> =7V, I <sub>ds</sub> =750mA	10.0	12.0		dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =7V, I <sub>ds</sub> =750mA f = 2GHz		45		%
<b>NF</b>	Noise Figure f = 2GHz V <sub>ds</sub> =5V, I <sub>ds</sub> =300mA V <sub>ds</sub> =5-7V, I <sub>ds</sub> =750mA		0.8 2.0		dB
<b>IP3</b>	Output 3rd Order Intercept Point f = 2GHz V <sub>ds</sub> =5-7V, I <sub>ds</sub> =750mA V <sub>ds</sub> =5V, I <sub>ds</sub> =300mA		48 39		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	880	1360	1760	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	560	720		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =14mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-11	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =4.8mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance		14*		°C/W

\* Overall R<sub>th</sub> depends on case mounting.

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	7V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	1.2A
<b>I<sub>gsf</sub></b>	Forward Gate Current	120mA	20mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	10 W	8.4 W

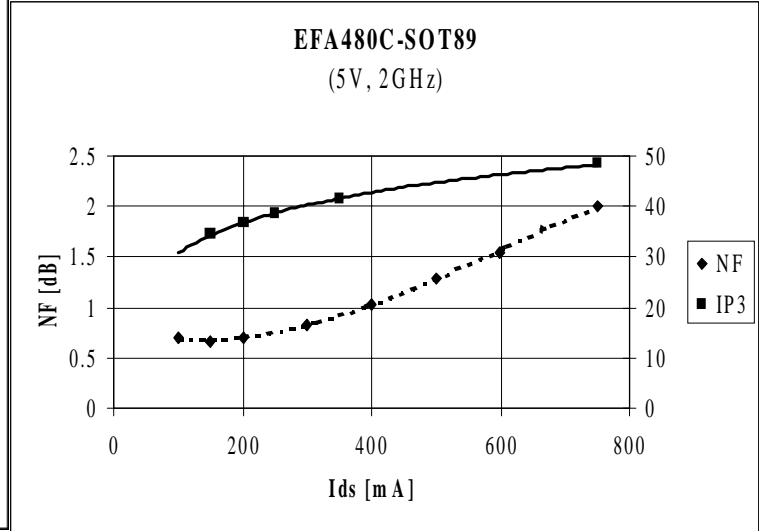
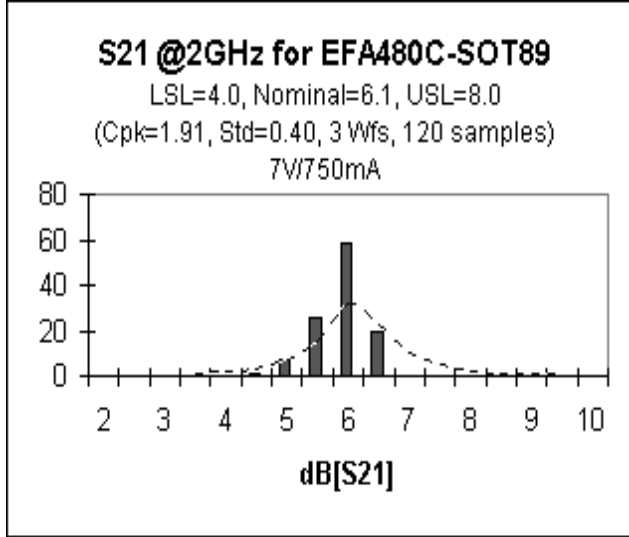
# EFA480C-SOT89

## DATA SHEET DC-4GHz Low Distortion GaAs Power FET

### Typical Performance

#### S21 Distribution

#### Noise Figure & IP3



### S-PARAMETERS

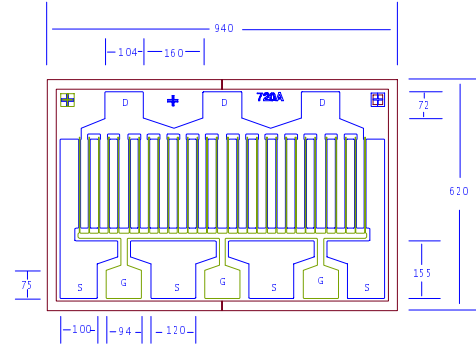
7V, 750mA									5V, 150mA								
Freq (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---		Freq (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG		MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.1	0.914	-74.6	18.618	138.4	0.015	56.1	0.552	-166.3	0.1	0.953	-71.1	17.133	141.6	0.018	68.2	0.586	-167.0
0.2	0.898	-113.3	12.814	117.4	0.024	39.5	0.652	-169.9	0.2	0.929	-111.0	12.353	120.2	0.026	39.7	0.678	-170.2
0.3	0.898	-134.4	9.412	105.5	0.025	31.1	0.677	-174.6	0.3	0.916	-133.1	9.150	107.7	0.031	29.3	0.712	-174.9
0.4	0.897	-147.5	7.342	97.4	0.026	28.5	0.692	-177.9	0.4	0.908	-146.6	7.156	99.3	0.030	28.1	0.731	-178.2
0.5	0.893	-156.3	5.983	91.3	0.028	25.9	0.698	178.6	0.5	0.902	-155.7	5.838	93.1	0.033	27.1	0.742	178.3
1.0	0.886	179.0	3.095	70.9	0.034	25.3	0.686	168.9	1.0	0.886	179.2	3.037	72.8	0.039	24.0	0.736	168.3
1.5	0.831	161.0	2.625	55.6	0.052	23.7	0.616	153.0	1.5	0.828	161.0	2.596	57.9	0.059	21.8	0.676	152.7
2.0	0.826	146.7	2.013	40.8	0.062	20.0	0.614	143.4	2.0	0.822	146.4	2.002	43.6	0.070	17.8	0.673	142.9
2.5	0.818	133.2	1.680	26.4	0.074	13.7	0.602	133.9	2.5	0.812	132.9	1.671	29.8	0.083	11.0	0.662	133.2
3.0	0.806	119.3	1.463	11.3	0.087	4.9	0.587	122.7	3.0	0.799	119.0	1.465	14.9	0.097	2.6	0.647	121.7
3.5	0.808	103.3	1.303	-5.2	0.100	-5.5	0.570	109.6	3.5	0.800	103.0	1.313	-1.0	0.111	-8.0	0.626	108.6
4.0	0.797	85.9	1.142	-23.4	0.110	-18.7	0.579	92.5	4.0	0.790	85.6	1.154	-18.7	0.120	-21.8	0.632	91.7
4.5	0.812	69.0	0.967	-40.5	0.113	-31.5	0.602	75.1	4.5	0.806	68.8	0.982	-35.4	0.124	-34.2	0.651	74.5
5.0	0.836	53.9	0.816	-56.0	0.113	-43.2	0.652	61.1	5.0	0.830	54.0	0.831	-50.4	0.123	-46.1	0.693	60.9
5.5	0.856	41.4	0.687	-69.8	0.109	-53.7	0.685	50.8	5.5	0.851	41.4	0.706	-63.8	0.120	-56.5	0.721	50.4
6.0	0.859	30.1	0.589	-82.8	0.108	-63.8	0.705	41.3	6.0	0.855	30.2	0.611	-76.3	0.118	-66.2	0.733	41.0

# EFA720A

## DATA SHEET

### Low Distortion GaAs Power FET

- +35.5dBm TYPICAL OUTPUT POWER
- 17.5dB TYPICAL POWER GAIN AT 2GHz
- 0.5 X 7200 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 120mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	33.5	35.5		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	16.0	17.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>		36		%
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1200	2040	2640	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	840	1100		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =20mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =7.2mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =7.2mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		6		°C/W

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	2.4A
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	34dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	23 W	19 W

# EFA720A

## DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.954	-139.8	7.651	105.9	0.018	25.1	0.664	-173.7
1.000	0.950	-160.3	4.004	92.2	0.019	20.5	0.680	-176.3
1.500	0.949	-168.0	2.694	84.8	0.020	22.1	0.685	-177.2
2.000	0.949	-172.3	2.027	79.1	0.020	25.1	0.689	-177.6
2.500	0.949	-175.1	1.624	74.1	0.021	28.5	0.692	-177.7
3.000	0.949	-177.3	1.354	69.5	0.022	32.1	0.696	-177.8
3.500	0.950	-179.1	1.161	65.2	0.023	35.5	0.700	-177.8
4.000	0.950	179.4	1.016	61.0	0.024	38.8	0.704	-177.9
4.500	0.951	178.1	0.903	57.0	0.025	41.8	0.709	-177.9
5.000	0.951	176.9	0.812	53.1	0.026	44.6	0.715	-178.0
5.500	0.952	175.7	0.737	49.3	0.028	47.2	0.720	-178.1
6.000	0.953	174.7	0.675	45.6	0.029	49.5	0.726	-178.2
6.500	0.953	173.6	0.621	42.0	0.031	51.6	0.733	-178.4
7.000	0.954	172.7	0.575	38.5	0.033	53.5	0.739	-178.6
7.500	0.955	171.7	0.535	35.1	0.034	55.2	0.746	-178.8
8.000	0.956	170.7	0.499	31.8	0.036	56.7	0.753	-179.0
8.500	0.957	169.8	0.468	28.6	0.038	58.0	0.760	-179.3
9.000	0.957	168.9	0.439	25.5	0.040	59.1	0.767	-179.6
9.500	0.958	168.0	0.413	22.6	0.042	60.1	0.774	-180.0
10.000	0.959	167.1	0.389	19.7	0.044	61.0	0.782	179.6

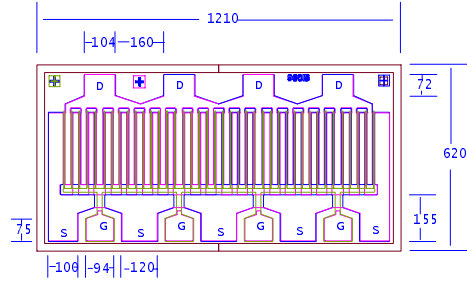
Note: The data included 0.7 mils diameter Au bonding wires:  
3 gate wires, 20 mils each; 3 drain wires, 12 mils each; 8 source wires, 7 mils each.

# EFA960B

## DATA SHEET

### Low Distortion GaAs Power FET

- +36.5dBm TYPICAL OUTPUT POWER
- 16.0dB TYPICAL POWER GAIN AT 2GHz
- 0.5 X 9600 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 160mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f= 2GHz 35.0	f= 4GHz 36.5	36.5	dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f= 2GHz 15.0	f= 4GHz 16.5	11.5	dB
<b>PAE</b>	Power Added Efficiency at 1dB Compression V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	f= 2GHz	34		%
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1600	2720	3520	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1450		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =25mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =9.6mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =9.6mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		5		°C/W

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	2.8A
<b>I<sub>gsf</sub></b>	Forward Gate Current	240mA	40mA
<b>P<sub>in</sub></b>	Input Power	35dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	27 W	23 W



# EFA960B

## DATA SHEET

### Low Distortion GaAs Power FET

#### S-PARAMETERS

8V, 1/2 Idss

FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.963	-150.4	6.232	100.8	0.015	20.2	0.741	-176.3
1.000	0.962	-165.8	3.195	89.5	0.015	18.3	0.750	-177.8
1.500	0.961	-171.5	2.140	83.1	0.016	21.0	0.753	-178.3
2.000	0.961	-174.6	1.608	77.9	0.016	24.7	0.755	-178.5
2.500	0.962	-176.7	1.287	73.2	0.017	28.6	0.758	-178.5
3.000	0.962	-178.3	1.072	68.9	0.018	32.5	0.761	-178.5
3.500	0.962	-179.6	0.919	64.7	0.018	36.2	0.764	-178.6
4.000	0.962	179.2	0.803	60.7	0.019	39.7	0.768	-178.6
4.500	0.963	178.2	0.713	56.8	0.020	42.9	0.772	-178.6
5.000	0.963	177.3	0.641	53.0	0.021	45.9	0.776	-178.6
5.500	0.964	176.4	0.582	49.3	0.022	48.6	0.781	-178.7
6.000	0.964	175.6	0.532	45.8	0.024	51.0	0.786	-178.8
6.500	0.965	174.8	0.490	42.3	0.025	53.2	0.791	-178.9
7.000	0.965	174.1	0.453	38.9	0.026	55.2	0.797	-179.0
7.500	0.966	173.3	0.421	35.7	0.028	56.9	0.802	-179.2
8.000	0.966	172.6	0.392	32.5	0.029	58.5	0.808	-179.4
8.500	0.967	171.9	0.367	29.5	0.031	59.9	0.814	-179.6
9.000	0.968	171.2	0.344	26.6	0.033	61.1	0.819	-179.8
9.500	0.968	170.5	0.324	23.7	0.034	62.2	0.825	179.9
10.000	0.969	169.8	0.305	21.0	0.036	63.2	0.831	179.6

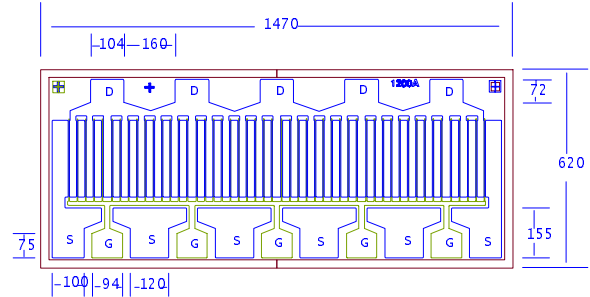
Note: The data included 0.7 mils diameter Au bonding wires:  
4 gate wires, 20 mils each; 4 drain wires, 12 mils each; 10 source wires, 7 mils each.

# EFA1200A

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

- +37.0dBm TYPICAL OUTPUT POWER
- 16.0dB TYPICAL POWER GAIN AT 2GHz
- 0.5 X 12,000 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION AND PLATED HEAT SINK
- ADVANCED EPITAXIAL DOPING PROFILE PROVIDES HIGH POWER EFFICIENCY, LINEARITY AND RELIABILITY
- Idss SORTED IN 200mA PER BIN RANGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f= 2GHz V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	35.5	37.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f= 2GHz V <sub>ds</sub> =8V, I <sub>ds</sub> =50% I <sub>dss</sub>	14.5	16.0		dB
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	2000	3400	4400	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1400	1800		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =30mA		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =12mA	-12	-15		V
<b>BV<sub>gs</sub></b>	Source Breakdown Voltage I <sub>gs</sub> =12mA	-7	-14		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		4		°C/W

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-4V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	2.0A
<b>I<sub>gsf</sub></b>	Forward Gate Current	300mA	50mA
<b>P<sub>in</sub></b>	Input Power	36dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	34 W	28 W

# EFA1200A

## PRELIMINARY DATA SHEET

### Low Distortion GaAs Power FET

S-PARAMETERS								
8V, 1/2 Idss								
FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.500	0.971	-156.3	5.096	98.0	0.012	17.9	0.794	-177.7
1.000	0.970	-168.7	2.590	88.2	0.013	17.8	0.799	-178.7
1.500	0.970	-173.2	1.732	82.3	0.013	21.4	0.801	-178.9
2.000	0.970	-175.7	1.300	77.4	0.013	25.7	0.803	-179.0
2.500	0.970	-177.4	1.040	73.0	0.014	30.1	0.805	-179.1
3.000	0.970	-178.7	0.867	68.8	0.015	34.3	0.807	-179.1
3.500	0.970	-179.8	0.743	64.8	0.015	38.2	0.810	-179.1
4.000	0.970	179.3	0.650	60.9	0.016	41.8	0.813	-179.1
4.500	0.971	178.5	0.577	57.2	0.017	45.1	0.816	-179.1
5.000	0.971	177.8	0.519	53.5	0.018	48.0	0.820	-179.2
5.500	0.971	177.1	0.471	50.0	0.019	50.7	0.823	-179.2
6.000	0.972	176.4	0.430	46.5	0.020	53.1	0.827	-179.3
6.500	0.972	175.8	0.396	43.2	0.021	55.3	0.831	-179.4
7.000	0.972	175.1	0.367	39.9	0.023	57.2	0.835	-179.5
7.500	0.973	174.5	0.341	36.8	0.024	59.0	0.840	-179.6
8.000	0.973	174.0	0.318	33.8	0.025	60.5	0.844	-179.8
8.500	0.974	173.4	0.297	30.9	0.027	61.9	0.849	-180.0
9.000	0.974	172.8	0.279	28.1	0.028	63.1	0.853	179.8
9.500	0.975	172.2	0.262	25.4	0.029	64.2	0.858	179.6
10.000	0.975	171.7	0.247	22.8	0.031	65.1	0.863	179.4

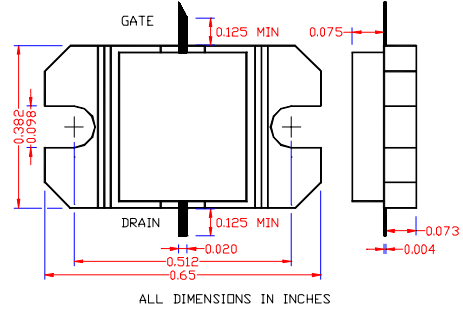
Note: The data included 0.7 mils diameter Au bonding wires:  
5 gate wires, 20 mils each; 5 drain wires, 12 mils each; 12 source wires, 7 mils each.

# EIA/EIB1011-2P

## PRELIMINARY DATA SHEET

### 10.7-11.7GHz, 2W Internally Matched Power FET

- 10.7-11.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.5/+33.0dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 9.5/8.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1011-2P			EIB1011-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	32.5	33.5		32	33.0		dBm
$G_{1dB}$	Gain at 1dB Compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	8.5	9.5		7.5	8.5		dB
PAE	Power Added Efficiency at 1dB compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		30			25		%
$I_{d1dB}$	Drain Current at 1dB Compression		880			850		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		40			46*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	1100	1440	1700	1100	1360	1700	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		1500			700		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=12\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=4.8\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=23\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

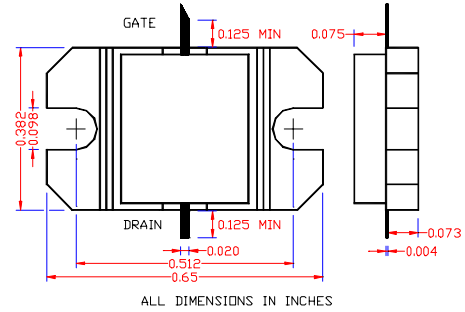
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	180mA	30mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	17W	14.2W

# EIA/EIB1011-4P

## PRELIMINARY DATA SHEET

### 10.7-11.7GHz, 4W Internally Matched Power FET

- 10.7-11.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(49dBm TYPICAL)
- +36.5/+35.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 9/8dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1011-4P			EIB1011-4P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	35.5	36.5		35	35.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	8	9		7	8		dB
PAE	Power Added Efficiency at 1dB compression $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		30			25		%
$I_{d1dB}$	Drain Current at 1dB Compression		1760			1700		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=10.7-11.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		43			49*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	2200	2880	3400	2200	2720	3400	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		3000			1400		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=24\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=9.6\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		4.5			4.5		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=26\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

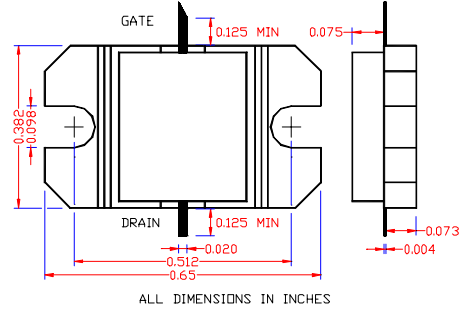
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	3120mA
$I_{gsf}$	Forward Gate Current	360mA	60mA
$P_{in}$	Input Power	35dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	30W	25W

# EIA/EIB1213-2P

## PRELIMINARY DATA SHEET

### 12.75-13.25GHz, 2W Internally Matched Power FET

- 12.75-13.25GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.5/+33.0dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 9.5/8.5dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1213-2P			EIB1213-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=12.75-13.25GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	32.5	33.5		32	33.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=12.75-13.25GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	8.5	9.5		7.5	8.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=12.75-13.25GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		30			25		%
<b>I<sub>d1dB</sub></b>	Drain Current at 1dB Compression		880			850		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=12.75-13.25GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		40			46*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1440	1700	1100	1360	1700	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		1500			700		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =12mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		°C/W

\*Typical -45dBc IM3 at P<sub>out</sub>=23dBm/Tone

### MAXIMUM RATINGS AT 25°C

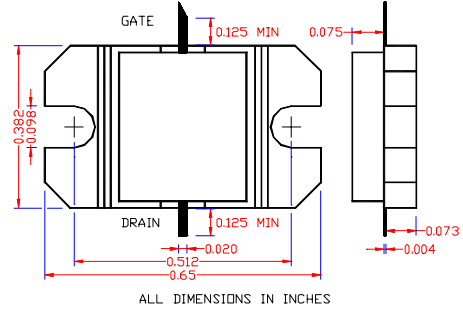
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	I <sub>dss</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	17W	14.2W

# EIA/EIB1213-4P

## PRELIMINARY DATA SHEET

### 12.75-13.25GHz, 4W Internally Matched Power FET

- 12.75-13.25GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(49dBm TYPICAL)
- +36.5/+35.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 9.5/8.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1213-4P			EIB1213-4P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=12.75\text{-}13.25\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	35.5	36.5		35	35.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=12.75\text{-}13.25\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	8.5	9.5		7.5	8.5		dB
PAE	Power Added Efficiency at 1dB compression $f=12.75\text{-}13.25\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		30			25		%
$I_{d1dB}$	Drain Current at 1dB Compression		1760			1700		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=12.75\text{-}13.25\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		43			49*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	2200	2880	3400	2200	2720	3400	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		3000			1400		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=24\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=9.6\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		4.5			4.5		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=26\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

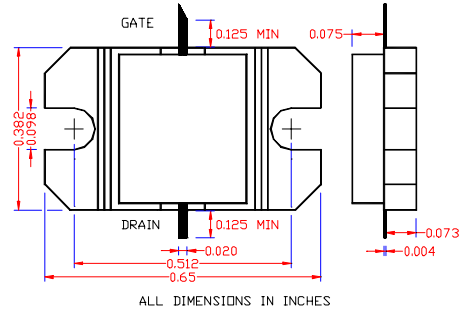
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	3120mA
$I_{gsf}$	Forward Gate Current	360mA	60mA
$P_{in}$	Input Power	35dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	30W	25W

# EIA/EIB1314-2P

## PRELIMINARY DATA SHEET

### 13.75-14.5GHz, 2W Internally Matched Power FET

- 13.75-14.5GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.5/+33.0dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 9.0/8.0dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1314-2P			EIB1314-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=13.75-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	32.5	33.5		32	33.0		dBm
$G_{1dB}$	Gain at 1dB Compression $f=13.75-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	8	9		7	8		dB
PAE	Power Added Efficiency at 1dB compression $f=13.75-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		30			25		%
$I_{d1dB}$	Drain Current at 1dB Compression		880			850		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=13.75-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		40			46*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	1100	1440	1700	1100	1360	1700	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		1500			700		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=12\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=4.8\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=23\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	180mA	30mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	17W	14.2W

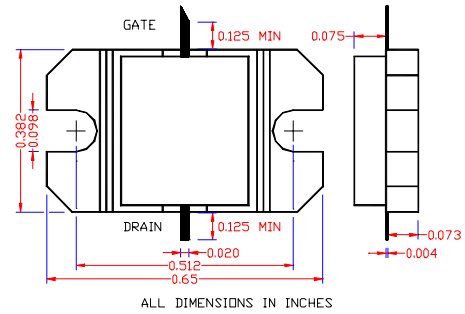


# EIA/EIB1314-4P

## PRELIMINARY DATA SHEET

### 13.75-14.5GHz, 4W Internally Matched Power FET

- 13.75-14.5GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 27% TYPICAL)
- EIB FEATURES HIGH IP3(49dBm TYPICAL)
- +36.5/+36dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 8.5/7.5dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1314-4P			EIB1314-4P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=13.75-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	35.5	36.5		35	36		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=13.75-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	7.5	8.5		6.5	7.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=13.75-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		27			22		%
<b>I<sub>d1dB</sub></b>	Drain Current at 1dB Compression		1760			1700		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=13.75-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		43			49*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	2200	2880	3400	2200	2720	3400	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		3000			1400		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =24mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =9.6mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		4.5			4.5		°C/W

\*Typical -45dBc IM3 at Pout=26dBm/Tone

### MAXIMUM RATINGS AT 25°C

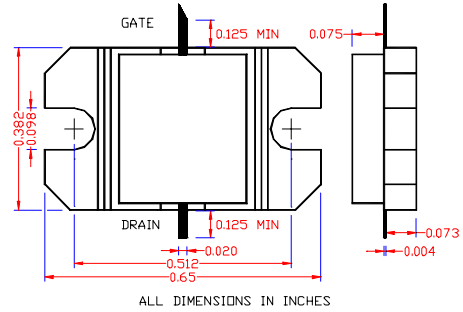
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	3120mA
<b>I<sub>gsf</sub></b>	Forward Gate Current	360mA	60mA
<b>P<sub>in</sub></b>	Input Power	35dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	30W	25W

# EIA/EIB1414-2P

## PRELIMINARY DATA SHEET

### 14.0-14.5GHz, 2W Internally Matched Power FET

- 14.0-14.5GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 30% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.5/+33.0dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 9.0/8.0dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1414-2P			EIB1414-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=14.0-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	33	33.5		32	33.0		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=14.0-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	8	9		7	8		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=14.0-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		30			25		%
<b>I<sub>d1dB</sub></b>	Drain Current at 1dB Compression		880			850		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=14.0-14.5GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		40			46*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1440	1700	1100	1360	1700	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		1500			700		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =12mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		°C/W

\*Typical -45dBc IM3 at Pout=23dBm/Tone

### MAXIMUM RATINGS AT 25°C

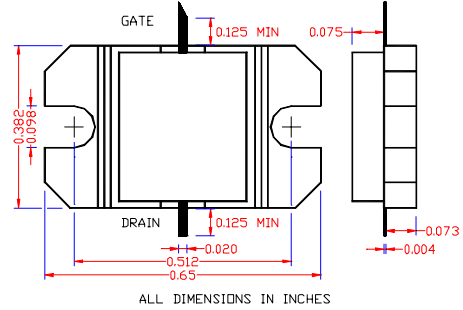
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	I <sub>dss</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	17W	14.2W

# EIA/EIB1414-4P

## PRELIMINARY DATA SHEET

### 14.0-14.5GHz, 4W Internally Matched Power FET

- 14.0-14.5GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 27% TYPICAL)
- EIB FEATURES HIGH IP3(49dBm TYPICAL)
- +36.5/+35.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 8.5/7.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1414-4P			EIB1414-4P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=14.0-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	35.5	36.5		35	35.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=14.0-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	7.5	8.5		6.5	7.5		dB
PAE	Power Added Efficiency at 1dB compression $f=14.0-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		27			22		%
$I_{d1dB}$	Drain Current at 1dB Compression		1760			1700		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=14.0-14.5\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		43			49*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	2200	2880	3400	2200	2720	3400	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		3000			1400		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=24\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=9.6\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		4.5			4.5		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=26\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

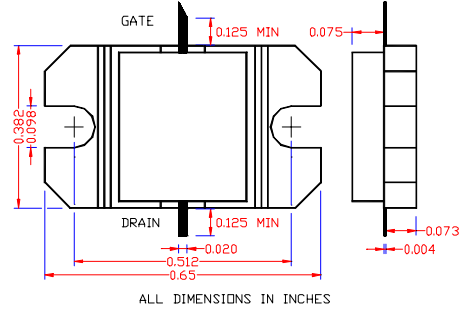
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	3120mA
$I_{gsf}$	Forward Gate Current	360mA	60mA
$P_{in}$	Input Power	35dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	30W	25W

# EIA/EIB1415-2P

## PRELIMINARY DATA SHEET

### 14.40-15.35GHz, 2W Internally Matched Power FET

- 14.40-15.35GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 27% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.0/+32.5dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 8.5/7.5dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1415-2P			EIB1415-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=14.40-15.35GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	32.5	33.0		32	32.5		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=14.40-15.35GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	7.5	8.5		6.5	7.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=14.40-15.35GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		27			22		%
<b>I<sub>d</sub>1dB</b>	Drain Current at 1dB Compression		880			850		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=14.40-15.35GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		40			46*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1440	1700	1100	1360	1700	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		1500			700		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>d</sub> s=12mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		°C/W

\*Typical -45dBc IM3 at Pout=23dBm/Tone

### MAXIMUM RATINGS AT 25°C

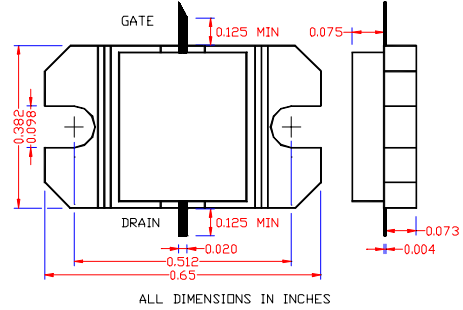
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	I <sub>dss</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	17W	14.2W

# EIA/EIB1415-4P

## PRELIMINARY DATA SHEET

### 14.40-15.35GHz, 4W Internally Matched Power FET

- 14.40-15.35GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 27% TYPICAL)
- EIB FEATURES HIGH IP3(49dBm TYPICAL)
- +36.0/+35.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 8/7dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1415-4P			EIB1415-4P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=14.40-15.35\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}(\text{EIA})$ , $0.6I_{dss}(\text{EIB})$	35.5	36.0		35	35.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=14.40-15.35\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}(\text{EIA})$ , $0.6I_{dss}(\text{EIB})$	7	8		6	7		dB
PAE	Power Added Efficiency at 1dB compression $f=14.40-15.35\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}(\text{EIA})$ , $0.6I_{dss}(\text{EIB})$		27			22		%
$I_{d1dB}$	Drain Current at 1dB Compression		1760			1700		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=14.40-15.35\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}(\text{EIA})$ , $0.6I_{dss}(\text{EIB})$		43			49*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	2200	2880	3400	2200	2720	3400	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		3000			1400		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=24\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=9.6\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		4.5			4.5		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=26\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

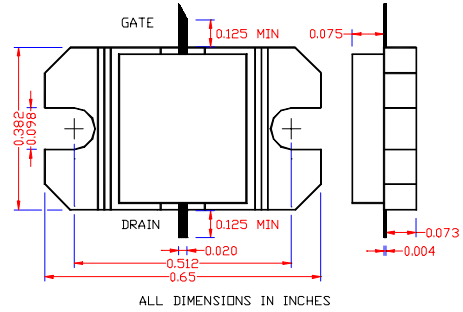
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	3120mA
$I_{gsf}$	Forward Gate Current	360mA	60mA
$P_{in}$	Input Power	35dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	30W	25W

# EIA1616-8P

## PRELIMINARY DATA SHEET

### 16.2-16.4GHz, 8W Internally Matched Power FET

- 16.2-16.4GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- HIGH PAE( 20% TYPICAL)
- +39dBm TYPICAL  $P_{1dB}$  OUTPUT POWER
- 6dB TYPICAL  $G_{1dB}$  POWER GAIN
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1616-8P						UNIT
		MIN	TYP	MAX				
$P_{1dB}$	Output Power at 1dB Compression $f=16.2-16.4\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$	38	39					dBm
$G_{1dB}$	Gain at 1dB Compression $f=16.2-16.4\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$	5	6					dB
PAE	Power Added Efficiency at 1dB compression $f=16.2-16.4\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$		20					%
$I_{d1dB}$	Drain Current at 1dB Compression		3520					mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=16.2-16.4\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$							dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	4400	5760	6800				mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		6000					mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=48\text{mA}$		-1.0	-2.5				V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=19.2\text{mA}$	-13	-15					V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		2.3					$^\circ\text{C}/\text{W}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

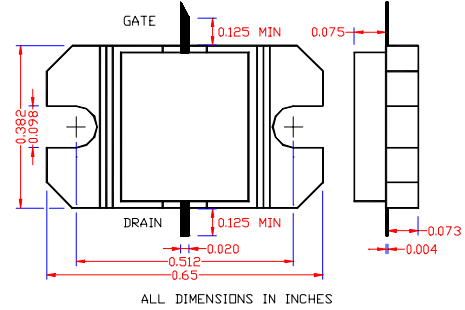
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	6240mA
$I_{gsf}$	Forward Gate Current	720mA	120mA
$P_{in}$	Input Power	38dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	60W	50W

# EIA/EIB1718A-1P

## PRELIMINARY DATA SHEET

### 17.3-18.1GHz, 1W Internally Matched Power FET

- 17.3-18.1GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(43dBm TYPICAL)
- +30.5/+29.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 7.5/6.0dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1718A-1P			EIB1718A-1P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=17.3-18.1\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	29	30.5		29.0	29.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=17.3-18.1\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	6.5	7.5		5.5	6.0		dB
PAE	Power Added Efficiency at 1dB compression $f=17.3-18.1\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		30			25		%
$I_{d1dB}$	Drain Current at 1dB Compression		440			425		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=17.3-18.1\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		37			43*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	550	720	850	550	720	850	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		760			360		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=6\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=2.4\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		16			16		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=20\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

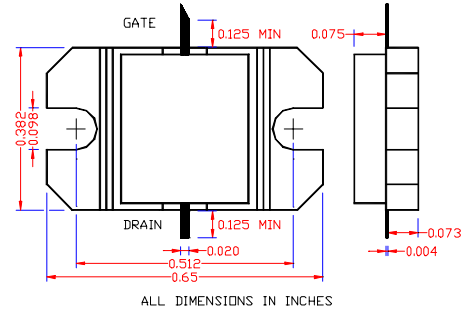
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	90mA	15mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	8.5	7.1W

# EIA/EIB1718A-2P

## PRELIMINARY DATA SHEET

### 17.3-18.1GHz, 2W Internally Matched Power FET

- 17.3-18.1GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.5/+32.5dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 7.5/5.5dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1718A-2P			EIB1718A-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=17.3-18.1GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	32.5	33.5		32.0	32.5		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=17.3-18.1GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	6.5	7.5		5.0	5.5		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=17.3-18.1GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		25			20		%
<b>I<sub>d</sub>1dB</b>	Drain Current at 1dB Compression		880			850		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=17.3-18.1GHz V <sub>ds</sub> =8V, I <sub>d</sub> sq=0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		40			46*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1440	1700	1100	1360	1700	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		1500			700		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>d</sub> s=12mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		°C/W

\*Typical -45dBc IM3 at Pout=23dBm/Tone

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	I <sub>dss</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	17W	14.2W

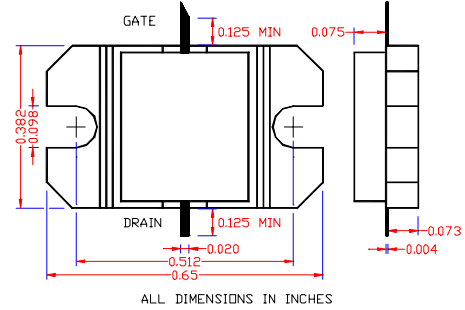


# EIA/EIB1718-1P

## PRELIMINARY DATA SHEET

### 17.7-18.7GHz, 1W Internally Matched Power FET

- 17.7-18.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(43dBm TYPICAL)
- +30.0/+29.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 6.5/5.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1718-1P			EIB1718-1P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=17.7-18.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	29	30.0		29.0	29.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=17.7-18.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	6.0	6.5		5.0	5.5		dB
PAE	Power Added Efficiency at 1dB compression $f=17.7-18.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		25			20		%
$I_{d1dB}$	Drain Current at 1dB Compression		440			425		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=17.7-18.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		37			43*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	550	720	850	550	720	850	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		760			360		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=6\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=2.4\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		16			16		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=20\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

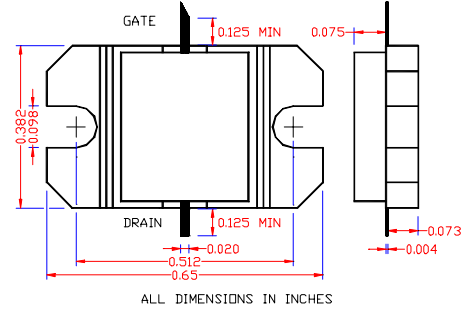
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	90mA	15mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	8.5W	7.1W

# EIA/EIB1718-2P

## PRELIMINARY DATA SHEET

### 17.7-18.7GHz, 2W Internally Matched Power FET

- 17.7-18.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.0/+32.5dBm TYPICAL P<sub>1dB</sub> OUTPUT POWER FOR EIA/EIB
- 6.0/5.0dB TYPICAL G<sub>1dB</sub> POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1718-2P			EIB1718-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
<b>P<sub>1dB</sub></b>	Output Power at 1dB Compression f=17.7-18.7GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	32.0	33.0		32.0	32.5		dBm
<b>G<sub>1dB</sub></b>	Gain at 1dB Compression f=17.7-18.7GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)	5.5	6.0		4.5	5.0		dB
<b>PAE</b>	Power Added Efficiency at 1dB compression f=17.7-18.7GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		25			20		%
<b>I<sub>d1dB</sub></b>	Drain Current at 1dB Compression		880			850		mA
<b>IP3</b>	Output 3 <sup>rd</sup> Order Intercept Point f=17.7-18.7GHz V <sub>ds</sub> =8V, I <sub>dsq</sub> =0.5 I <sub>dss</sub> (EIA), 0.6I <sub>dss</sub> (EIB)		40			46*		dBm
<b>I<sub>dss</sub></b>	Saturated Drain Current V <sub>ds</sub> =3V, V <sub>gs</sub> =0V	1100	1440	1700	1100	1360	1700	mA
<b>G<sub>m</sub></b>	Transconductance V <sub>ds</sub> =3V, V <sub>gs</sub> =0V		1500			700		mS
<b>V<sub>p</sub></b>	Pinch-off Voltage V <sub>ds</sub> =3V, I <sub>ds</sub> =12mA		-1.0	-2.5		-2.0	-3.5	V
<b>BV<sub>gd</sub></b>	Drain Breakdown Voltage I <sub>gd</sub> =4.8mA	-13	-15			-15		V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		°C/W

\*Typical -45dBc IM3 at Pout=23dBm/Tone

### MAXIMUM RATINGS AT 25°C

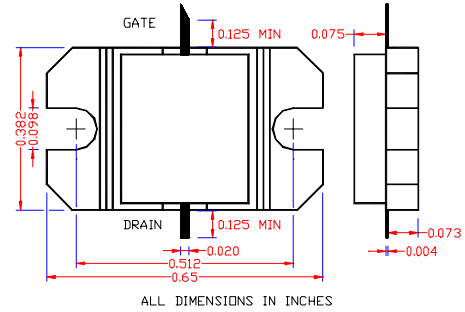
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	I <sub>dss</sub>
<b>I<sub>gsf</sub></b>	Forward Gate Current	180mA	30mA
<b>P<sub>in</sub></b>	Input Power	32dBm	@ 3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	17W	14.2W

# EIA/EIB1818-1P

## PRELIMINARY DATA SHEET

### 18.15-18.75GHz, 1W Internally Matched Power FET

- 18.15-18.75GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(43dBm TYPICAL)
- +30.0/+29.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 6.5/5.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1818-1P			EIB1818-1P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	29	30.0		29.0	29.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	6.0	6.5		5.0	5.5		dB
PAE	Power Added Efficiency at 1dB compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		25			20		%
$I_{d1dB}$	Drain Current at 1dB Compression		440			425		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		37			43*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	550	720	850	550	720	850	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		760			360		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=6\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=2.4\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		16			16		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=20\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

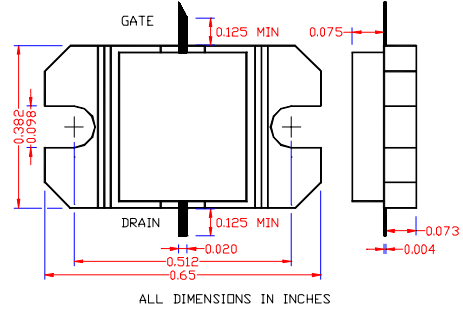
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	90mA	15mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	8.5W	7.1W

# EIA/EIB1818-2P

## PRELIMINARY DATA SHEET

### 18.15-18.75GHz, 2W Internally Matched Power FET

- 18.15-18.75GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.0/+32.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 6.0/5.0dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1818-2P			EIB1818-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	32.0	33.0		32.0	32.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	5.5	6.0		4.5	5.0		dB
PAE	Power Added Efficiency at 1dB compression $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		25			20		%
$I_{d1dB}$	Drain Current at 1dB Compression		880			850		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=18.15-18.75\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		40			46*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	1100	1440	1700	1100	1360	1700	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		1500			700		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=12\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=4.8\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=23\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

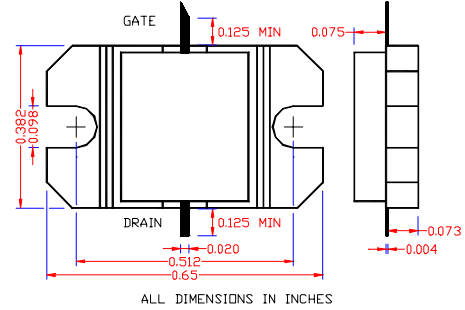
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	180mA	30mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	17W	14.2W

# EIA/EIB1819-1P

## PRELIMINARY DATA SHEET

### 18.7-19.7GHz, 1W Internally Matched Power FET

- 18.7-19.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(43dBm TYPICAL)
- +30.0/+29.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 6.5/5.5dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1819-1P			EIB1819-1P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	29	30.0		29.0	29.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	6.0	6.5		5.0	5.5		dB
PAE	Power Added Efficiency at 1dB compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		25			20		%
$I_{d1dB}$	Drain Current at 1dB Compression		440			425		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		37			43*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	550	720	850	550	720	850	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		760			360		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=6\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=2.4\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		16			16		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=20\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

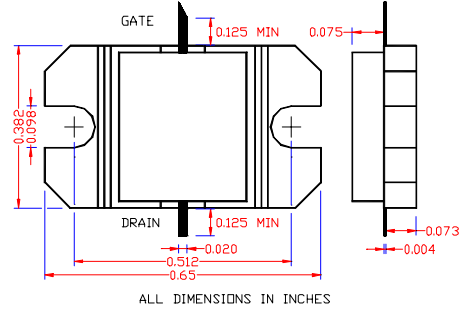
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	90mA	15mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	8.5W	7.1W

# EIA/EIB1819-2P

## PRELIMINARY DATA SHEET

### 18.7-19.7GHz, 2W Internally Matched Power FET

- 18.7-19.7GHz BANDWIDTH AND INPUT/OUTPUT IMPEDANCE MATCHED TO 50 OHM
- EIA FEATURES HIGH PAE( 25% TYPICAL)
- EIB FEATURES HIGH IP3(46dBm TYPICAL)
- +33.0/+32.5dBm TYPICAL  $P_{1dB}$  OUTPUT POWER FOR EIA/EIB
- 6.0/5.0dB TYPICAL  $G_{1dB}$  POWER GAIN FOR EIA/EIB
- NON-HERMETIC METAL FLANGE PACKAGE



### ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

SYMBOLS	PARAMETERS/TEST CONDITIONS	EIA1819-2P			EIB1819-2P			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
$P_{1dB}$	Output Power at 1dB Compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	32.0	33.0		32.0	32.5		dBm
$G_{1dB}$	Gain at 1dB Compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)	5.5	6.0		4.5	5.0		dB
PAE	Power Added Efficiency at 1dB compression $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		25			20		%
$I_{d1dB}$	Drain Current at 1dB Compression		880			850		mA
IP3	Output 3 <sup>rd</sup> Order Intercept Point $f=18.7-19.7\text{GHz}$ $V_{ds}=8\text{V}$ , $I_{dsq}=0.5 I_{dss}$ (EIA), $0.6I_{dss}$ (EIB)		40			46*		dBm
$I_{dss}$	Saturated Drain Current $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$	1100	1440	1700	1100	1360	1700	mA
$G_m$	Transconductance $V_{ds}=3\text{V}$ , $V_{gs}=0\text{V}$		1500			700		mS
$V_p$	Pinch-off Voltage $V_{ds}=3\text{V}$ , $I_{ds}=12\text{mA}$		-1.0	-2.5		-2.0	-3.5	V
$BV_{gd}$	Drain Breakdown Voltage $I_{gd}=4.8\text{mA}$	-13	-15			-15		V
$R_{th}$	Thermal Resistance (Au-Sn Eutectic Attach)		8			8		$^\circ\text{C}/\text{W}$

\*Typical -45dBc IM3 at  $P_{out}=23\text{dBm}/\text{Tone}$

### MAXIMUM RATINGS AT $25^\circ\text{C}$

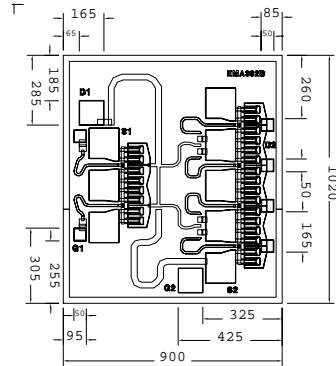
SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
$V_{ds}$	Drain-Source Voltage	12V	8V
$V_{gs}$	Gate-Source Voltage	-8V	-3V
$I_{ds}$	Drain Current	$I_{dss}$	$I_{dss}$
$I_{gsf}$	Forward Gate Current	180mA	30mA
$P_{in}$	Input Power	32dBm	@ 3dB Compression
$T_{ch}$	Channel Temperature	175 $^\circ\text{C}$	150 $^\circ\text{C}$
$T_{stg}$	Storage Temperature	-65/175 $^\circ\text{C}$	-65/150 $^\circ\text{C}$
$P_t$	Total Power Dissipation	17W	14.2W

# EMA302B

## PRELIMINARY DATA SHEET

### 22-26 GHz Medium Power MMIC

- 22-26 GHz BANDWIDTH
- +28.0 dBm TYPICAL OUTPUT POWER
- 15 dB  $\pm$  1.5 dB TYPICAL POWER GAIN
- TWO STAGE, INPUT PARTIALLY MATCHED, OUTPUT MATCH OFF CHIP
- 0.3 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL HETEROJUNCTION PROFILE PROVIDES EXTRA HIGH POWER EFFICIENCY, AND HIGH RELIABILITY



### ELECTRICAL CHARACTERISTICS<sup>1</sup> (T<sub>a</sub> = 25 °C)

SYMBOL	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>F</b>	Operating Frequency Range	22		26	GHz
<b>P<sub>1dB</sub></b>	Output Power at 1dB Gain Compression		28		dBm
<b>G<sub>ss</sub></b>	Small Signal Gain		15		dB
<b>PAE</b>	Power added efficiency at 1dB gain Compression		24		%
<b>VSWR<sub>in</sub></b>	Input VSWR		2.5:1		
<b>VSWR<sub>out</sub></b>	Output VSWR		3.0:1		
<b>I<sub>ds1</sub>/I<sub>ds2</sub></b>	Drain Supply Currents for 1 <sup>st</sup> & 2 <sup>nd</sup> Stages		120/240		mA
<b>V<sub>dd</sub></b>	Power Supply Voltage		6	8	V
<b>R<sub>th</sub></b>	Thermal Resistance (Au-Sn Eutectic Attach)		18		°C/W

Note: 1. Specifications are based on device mounted in application circuit.  
D.C. characteristics for 1<sup>st</sup> & 2<sup>nd</sup> FETs follow those of EPA080A and EPA160A, respectively.

### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>2</sup>	CONTINUOUS <sup>3</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds1</sub>/I<sub>ds2</sub></b>	Drain Current	I <sub>dss</sub>	260 mA / 520 mA
<b>I<sub>gs1</sub>/I<sub>gs2</sub></b>	Forward Gate Current	40 mA / 80 mA	7mA / 14 mA
<b>P<sub>in</sub></b>	Input Power	25dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	7.5 W	6.3 W

## PRELIMINARY DATA SHEET

## 22-26 GHz Medium Power MMIC

S-PARAMETERS								
(CHIP WITHOUT EXTERNAL MATCHING CIRCUIT)								
8V, 1/2 Idss								
FREQ	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1	0.955	-72.5	0.396	-138.9	0.000	177.5	0.019	-164.0
2	0.959	-110.2	6.670	107.4	0.001	73.5	0.155	-66.5
3	1.046	-126.7	10.324	-37.5	0.001	172.1	0.307	-100.9
4	1.061	-145.3	6.669	-15.9	0.004	165.1	0.346	-102.5
5	1.075	-156.4	15.100	-72.7	0.009	143.1	0.686	-101.5
6	0.916	-164.1	11.585	-154.3	0.010	100.1	0.754	-147.9
7	0.913	-163.5	5.883	172.1	0.007	95.3	0.536	-152.7
8	0.925	-164.5	3.726	154.9	0.007	103.4	0.484	-147.5
9	0.926	-165.4	2.660	142.4	0.009	108.3	0.484	-143.2
10	0.933	-165.4	2.109	133.0	0.005	100.8	0.517	-139.2
11	0.939	-165.7	1.747	123.3	0.006	115.3	0.543	-138.2
12	0.938	-164.6	1.520	114.7	0.007	117.3	0.571	-139.3
13	0.936	-164.4	1.372	106.1	0.008	131.5	0.598	-140.6
14	0.935	-165.7	1.278	97.5	0.008	121.1	0.631	-141.3
15	0.934	-167.8	1.229	88.1	0.008	120.0	0.649	-142.0
16	0.933	-168.4	1.249	79.2	0.008	104.3	0.679	-143.5
17	0.924	-169.2	1.272	68.3	0.007	111.8	0.695	-147.6
18	0.910	-172.3	1.358	56.3	0.010	84.6	0.743	-150.3
19	0.895	179.7	1.486	43.5	0.006	91.2	0.767	-147.5
20	0.868	171.0	1.688	28.1	0.006	87.5	0.797	-145.3
21	0.809	171.2	2.027	10.4	0.006	89.1	0.835	-154.2
22	0.713	164.0	2.606	-13.9	0.004	73.0	0.881	-156.3
22.5	0.613	162.1	3.032	-30.7	0.004	63.4	0.895	-159.4
23	0.473	164.8	3.459	-51.3	0.002	66.1	0.923	-162.8
23.5	0.347	-176.7	3.728	-76.5	0.003	121.7	0.926	-166.6
24	0.400	-147.1	3.618	-103.8	0.007	133.1	0.922	-169.1
24.5	0.558	-139.4	3.175	-129.8	0.009	122.1	0.897	-170.7
25	0.684	-141.3	2.647	-152.3	0.012	114.1	0.874	-169.7
25.5	0.764	-145.0	2.135	-171.9	0.012	99.9	0.861	-169.7
26	0.810	-147.9	1.708	170.0	0.014	90.0	0.879	-169.4
27	0.891	-153.0	1.142	141.0	0.014	85.5	0.870	-165.1
28	0.929	-156.3	0.750	113.7	0.016	84.5	0.851	-163.6
29	0.956	-156.5	0.502	91.7	0.019	81.6	0.839	-162.0
30	0.968	-155.1	0.338	78.3	0.026	64.0	0.852	-163.2
31	0.975	-152.8	0.228	52.3	0.018	49.3	0.846	-160.7
32	0.981	-153.0	0.157	31.8	0.013	54.7	0.856	-158.2
33	0.983	-154.1	0.118	14.7	0.012	57.3	0.902	-157.0
34	0.988	-153.9	0.113	-20.8	0.017	48.1	0.772	-160.7
35	0.983	-154.0	0.035	-18.1	0.011	78.3	0.879	-157.1
36	0.988	-155.5	0.025	-38.4	0.007	85.2	0.881	-157.3
37	0.997	-158.4	0.012	-53.2	0.007	107.8	0.867	-158.0
38	1.007	-157.6	0.006	112.6	0.009	109.7	0.862	-163.6
39	1.004	-153.8	0.002	165.9	0.008	89.1	0.851	-172.9
40	0.981	-154.9	0.015	-101.3	0.008	56.0	0.871	-177.9

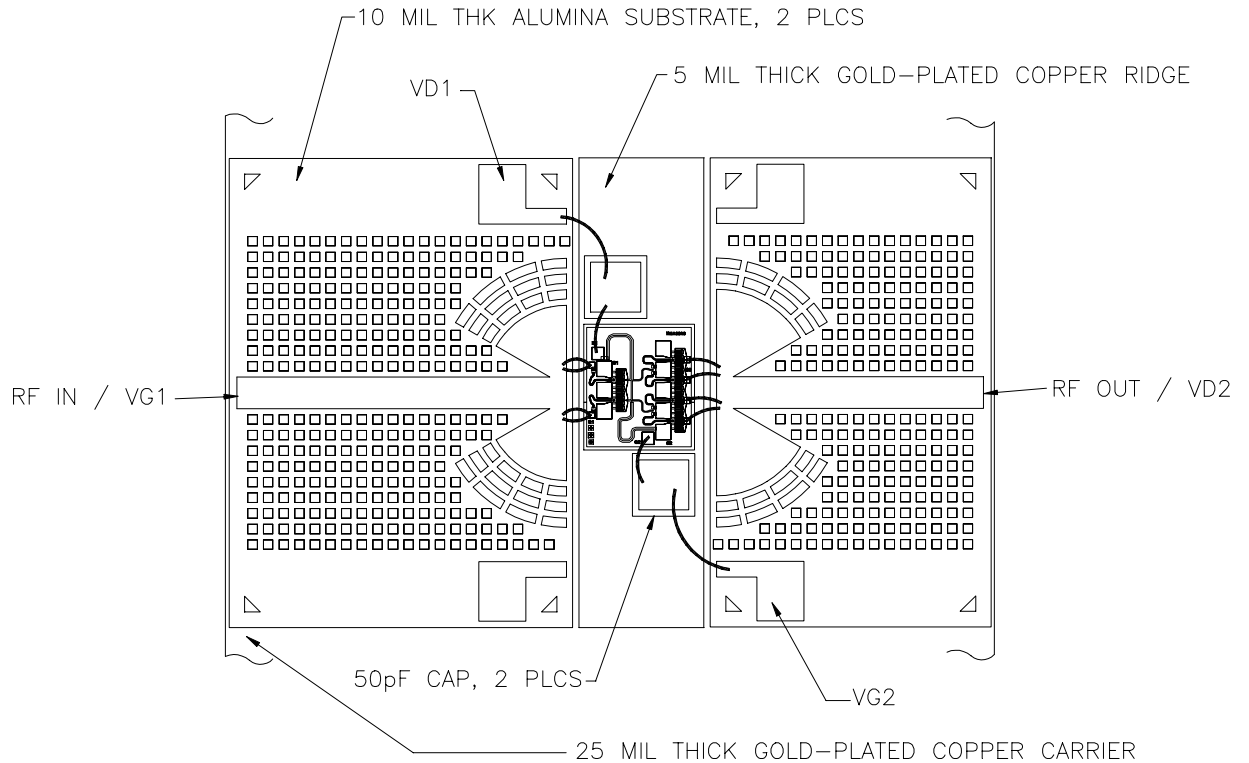
Note: The data included 0.7 mils diameter au bonding wires:  
2 input wires, 10 mils each; 4 output wires, 12 mils each.



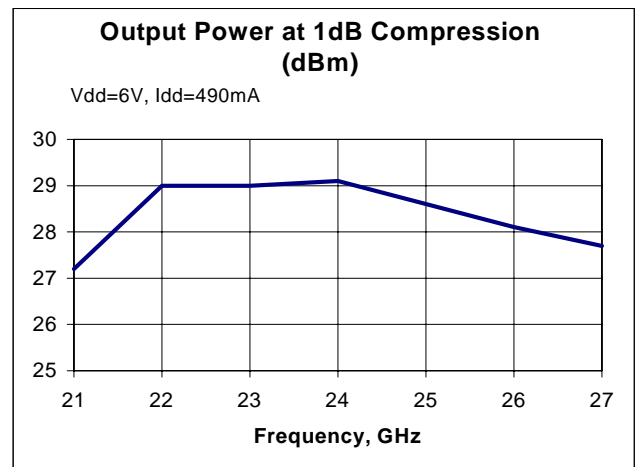
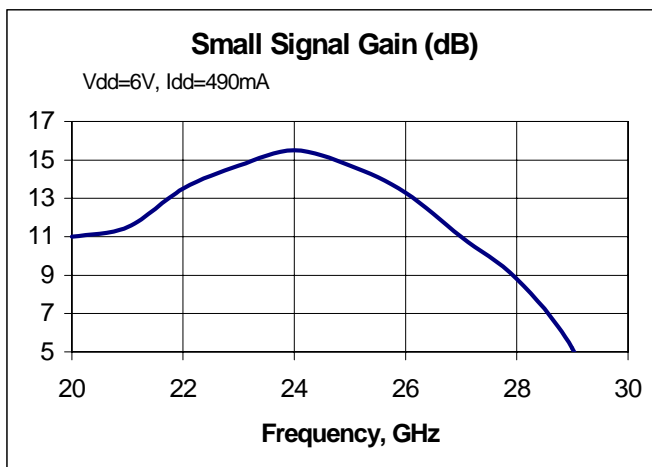
## PRELIMINARY DATA SHEET

### 22-26 GHz Medium Power MMIC

#### TYPICAL APPLICATION CIRCUIT



#### TYPICAL APPLICATION PERFORMANCE CHARACTERISTICS



#### APPLICATION HINTS

The device should be die attached with Gold-Tin eutectic. Epoxy die attach is not recommended. Thermocompression bonding of .7 mil to 1 mil diameter gold wire is recommended.

The EMA302B is partially input matched. Some input match and the output match must be provided off-chip. This allows the use of optimal materials for matching networks to minimize loss, and provides for flexibility to optimize the match for the application frequency. Typically the bond wire inductance will form part of the matching network, so bond wire lengths must be controlled and repeatable.

The sources of the transistors are directly via-hole grounded. A negative voltage is required to bias the gates of the transistors. The gate voltage for the input stage must be provided at the RF input bonding pad, and the drain current for the output stage must be provided through the output bonding pad. Appropriate bias networks must be provided off chip. Typically a quarter wave microstrip line or bond wire will suffice. Adequate DC blocking and bypassing must also be provided. A series resistance of about 50 ohms is recommended in the gate DC bias circuit of each FET to limit gate current and suppress low frequency oscillations. The drain bias circuits should be well bypassed down to MHz frequencies to prevent oscillations. Some isolation should be provided between the two drain circuits at GHz frequencies to prevent oscillations. Although there is some bypassing on chip of the VD1 and VG2 terminals, additional bypass capacitors, placed close to the chip, are recommended.

The gate and drain power supplies should be sequenced to turn on the negative gate voltage before the positive drain voltage is applied. Turning on the full drain voltage before the gate voltage can cause excessive power dissipation or destructive oscillations.

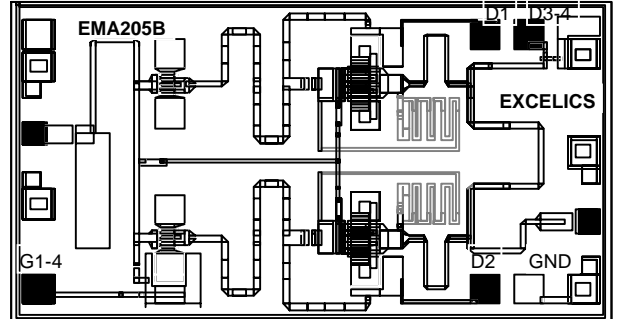
# EMA205B

## TENTATIVE DATA SHEET

### 9-16 GHz Low Noise MMIC

#### FEATURES

- 9-16 GHz BANDWIDTH
- +18.0 dBm TYPICAL OUTPUT POWER
- 14 dB  $\pm$  1.5 dB TYPICAL POWER GAIN
- TWO SECTION, DISTRIBUTED AMPLIFIER
- DUAL BIAS SUPPLY
- 0.3 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL HETEROJUNCTION PROFILE PROVIDES EXTRA HIGH POWER EFFICIENCY, AND HIGH RELIABILITY



#### ELECTRICAL CHARACTERISTICS<sup>1</sup> (T<sub>a</sub> = 25 °C)

SYMBOL	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>F</b>	Operating Frequency Range	9		16	GHz
<b>P<sub>1dB</sub></b>	Output Power at 1dB Gain Compression		18		dBm
<b>G<sub>ss</sub></b>	Small Signal Gain		14		dB
<b>ΔG<sub>ss</sub></b>	Small Signal Gain Flatness		$\pm$ 1.5		dB
<b>NF</b>	Noise Figure		4		dB
<b>VSWR in</b>	Input VSWR		1.5:1		
<b>VSWR out</b>	Output VSWR		2.0:1		
<b>I<sub>dd</sub></b>	Power Supply Current		160		mA
<b>V<sub>dd</sub></b>	Power Supply Voltage		5	8	V

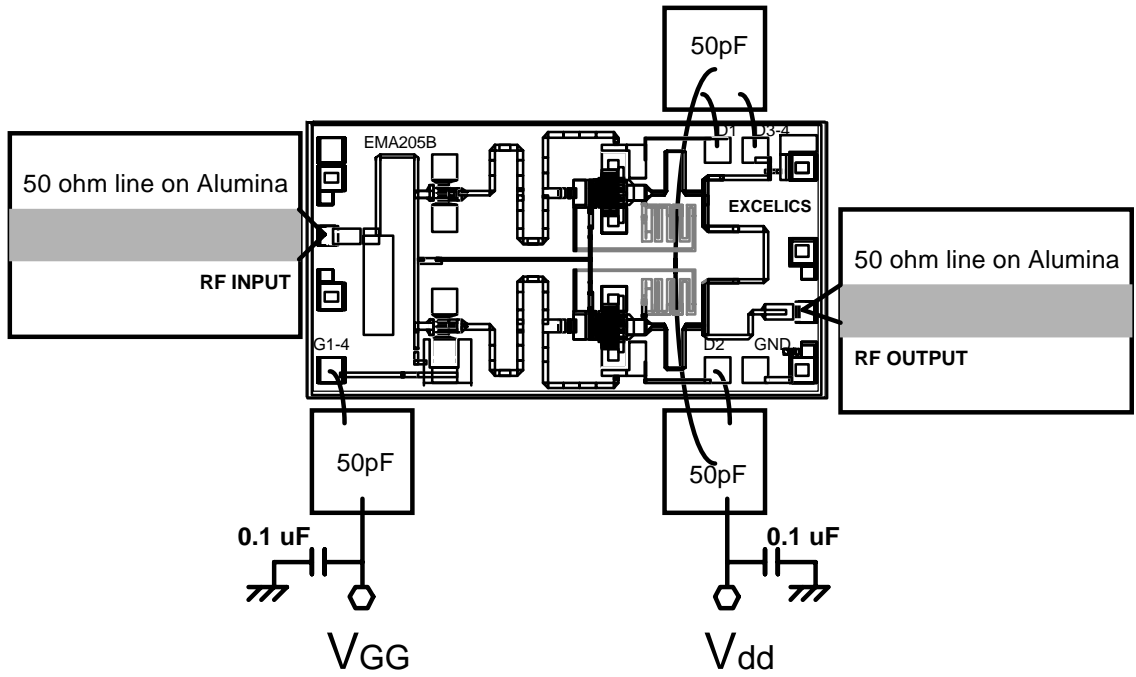
#### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
<b>V<sub>ds</sub></b>	Drain-Source Voltage	12V	8V
<b>V<sub>gs</sub></b>	Gate-Source Voltage	-8V	-3V
<b>I<sub>ds</sub></b>	Drain Current	I <sub>dss</sub>	225mA
<b>I<sub>gf</sub></b>	Forward Gate Current	55 mA	9mA
<b>P<sub>in</sub></b>	Input Power	13dBm	@3dB Compression
<b>T<sub>ch</sub></b>	Channel Temperature	175°C	150°C
<b>T<sub>stg</sub></b>	Storage Temperature	-65/175°C	-65/150°C
<b>P<sub>t</sub></b>	Total Power Dissipation	1.1 W	900 mW

**TENTATIVE DATA SHEET****9-16 GHz Low Noise MMIC****S-PARAMETERS** ( On wafer  $S_{ij}$  measurements )5V, 1/2  $I_{dss\_6}$ 

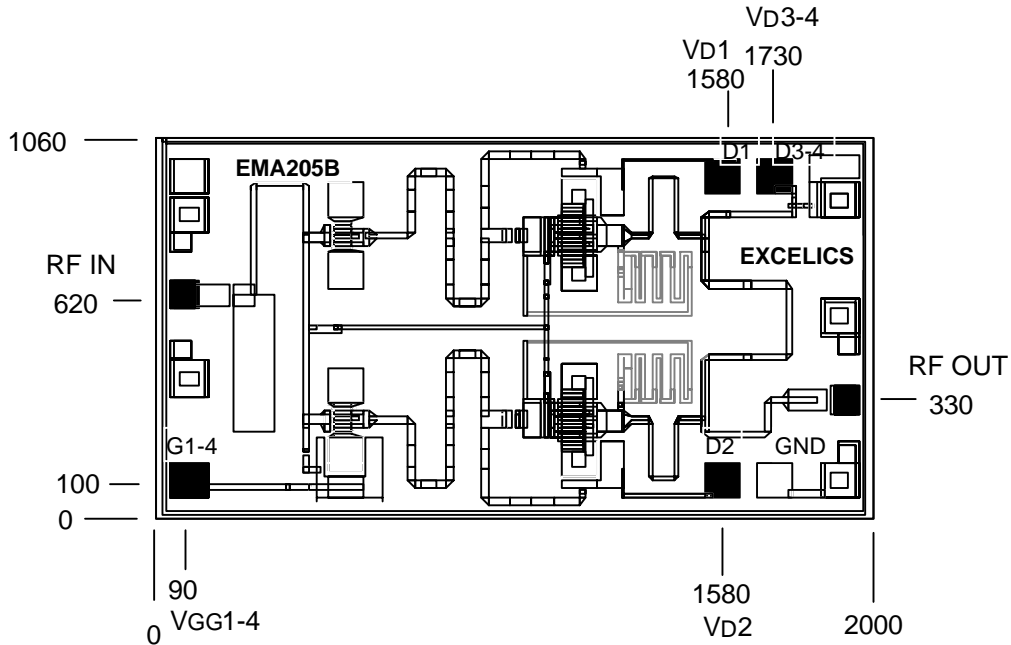
FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
1	0.365	-129.2	0.276	82.1	0.0038	-28.6	0.620	-112.2
2	0.471	-172.2	0.441	47.4	0.0011	-88.5	0.844	-167.7
3	0.450	172.4	0.416	3.6	0.0008	-125.9	0.810	158.0
4	0.422	162.0	0.389	16.1	0.0006	-139.8	0.732	130.9
5	0.389	154.2	0.826	35.4	0.0007	-175.1	0.614	104.5
6	0.350	148.0	1.825	8.7	0.0011	160.0	0.430	73.8
7	0.312	143.6	3.185	-29.7	0.0020	139.7	0.185	34.2
8	0.276	141.4	4.559	-73.3	0.0030	97.5	0.078	-139.8
9	0.250	138.6	5.385	-117.5	0.0037	58.0	0.245	168.1
10	0.234	136.9	5.626	-159.0	0.0045	18.1	0.300	137.5
11	0.226	139.7	5.497	166.2	0.0052	-10.6	0.275	115.0
12	0.221	141.9	5.350	136.0	0.0052	-34.2	0.214	99.9
13	0.222	140.6	5.326	107.4	0.0060	-54.4	0.149	95.2
14	0.220	135.3	5.360	79.5	0.0067	-76.5	0.092	109.1
15	0.235	131.2	5.594	50.3	0.0077	-103.0	0.088	149.1
16	0.271	127.6	6.062	18.7	0.0101	-130.2	0.132	172.4
17	0.385	119.2	6.709	-17.2	0.0122	-160.7	0.205	176.3
18	0.511	89.3	6.771	-59.4	0.0122	160.1	0.314	172.1
19	0.577	53.6	5.973	-105.7	0.0111	115.1	0.457	159.6
20	0.577	21.6	4.309	-151.4	0.0072	74.4	0.608	141.4
21	0.564	-2.5	2.567	171.8	0.0022	33.0	0.711	119.8
22	0.589	-23.7	1.423	155.1	0.0004	127.1	0.733	98.4
23	0.606	-42.8	1.095	146.8	0.0018	108.7	0.686	81.3
24	0.623	-58.4	0.917	130.5	0.0021	87.5	0.628	69.0
25	0.6426	-70.4	0.754	112.2	0.0023	72.2	0.585	59.3
26	0.664	-79.7	0.607	94.3	0.0027	75.1	0.555	50.8
27	0.694	-88.2	0.487	76.6	0.0031	76.8	0.531	42.8
28	0.732	-98.1	0.399	58.6	0.0026	68.9	0.511	34.9
29	0.761	-106.2	0.330	41.6	0.0015	58.9	0.496	27.0
30	0.791	-114.1	0.271	24.2	0.0014	23.6	0.480	19.1

# ASSEMBLY DRAWING



The length of RF wires should be as short as possible. Use at least two wires between RF pad and 50 ohm line and separate the wires to minimize the mutual inductance.

# CHIP OUTLINE

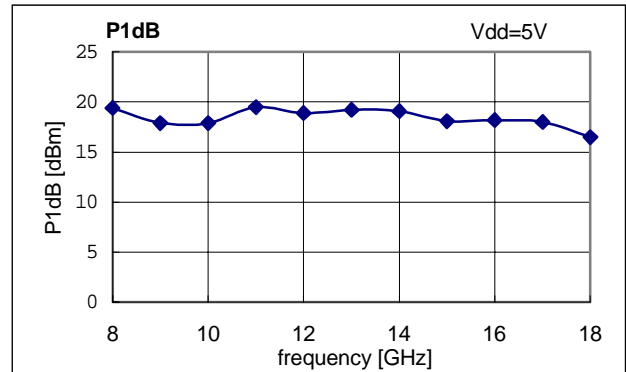
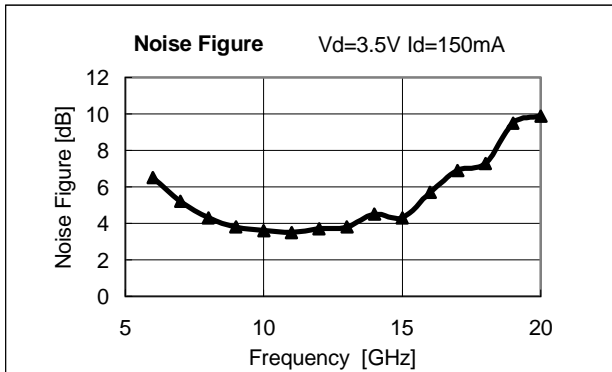
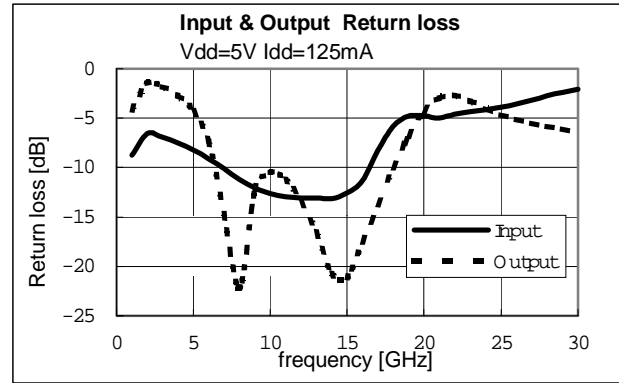
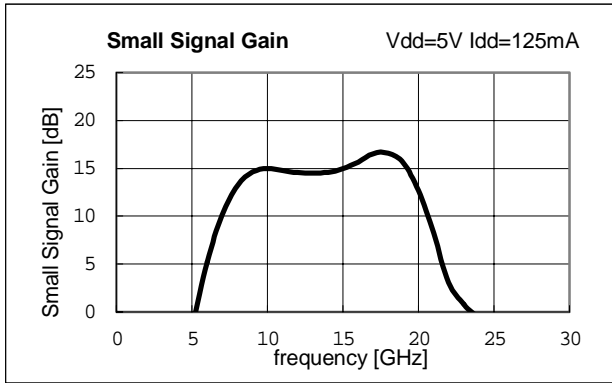


Chip Size 1060 x 2000 microns  
 Chip Thickness:  $75 \pm 13$  microns  
 PAD Dimensions: 1. DC 100 x 100 microns  
 2. RF 80 x 68 microns  
 All Dimensions In Microns

## TENTATIVE DATA SHEET

### 9-16 GHz Low Noise MMIC

#### TYPICAL APPLICATION PERFORMANCE



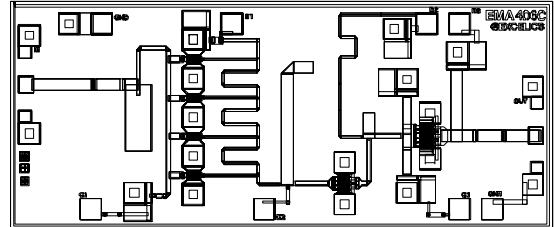
# EMA406C

## TENTATIVE DATA SHEET

### 26 - 32 GHz Low Noise MMIC

#### FEATURES

- 26 -32 GHz BANDWIDTH
- +20.0 dBm TYPICAL OUTPUT POWER
- 21 dB  $\pm$  1.5 dB TYPICAL POWER GAIN
- FOUR SECTION, DISTRIBUTED AMPLIFIER
- DUAL BIAS SUPPLY
- 0.3 MICRON RECESSED "MUSHROOM" GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL HETEROJUNCTION



PROFILE PROVIDES EXTRA HIGH POWER EFFICIENCY, AND HIGH RELIABILITY

#### ELECTRICAL CHARACTERISTICS<sup>1</sup> (T<sub>a</sub> = 25 °C)

SYMBOL	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
F	Operating Frequency Range	26		32	GHz
P <sub>1dB</sub>	Output Power at 1dB Gain Compression		20		dBm
G <sub>ss</sub>	Small Signal Gain		21		dB
$\Delta$ G <sub>ss</sub>	Small Signal Gain Flatness		$\pm$ 1.5		dB
NF	Noise Figure		6		dB
VSWR <sub>in</sub>	Input VSWR		2.0:1		
VSWR <sub>out</sub>	Output VSWR		3.0:1		
I <sub>dd</sub>	Power Supply Current		140		mA
V <sub>dd</sub>	Power Supply Voltage		5	8	V

#### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-3V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	215mA
I <sub>gf</sub>	Forward Gate Current	50 mA	8.5mA
P <sub>in</sub>	Input Power	15dBm	@3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	1 W	0.85 W

## TENTATIVE DATA SHEET

### 26 - 32 GHz Low Noise MMIC

S-PARAMETERS ( On wafer $S_{ij}$ measurements )								
5V, 1/2 $I_{dss}$								
FREQ (GHz)	--- S11 ---		--- S21 ---		--- S12 ---		--- S22 ---	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
20.00	0.33	77.79	1.28	-95.95	0.0008	44.60	0.96	85.42
20.50	0.32	68.81	1.41	-106.07	0.0011	42.01	0.96	80.89
21.00	0.30	59.18	1.57	-115.93	0.0010	52.46	0.97	75.97
21.50	0.29	48.60	1.79	-125.92	0.0014	89.17	0.97	70.79
22.00	0.27	37.50	2.09	-136.41	0.0016	91.70	0.98	65.27
22.50	0.25	25.58	2.49	-147.65	0.0006	98.47	0.99	59.31
23.00	0.24	11.90	3.02	-159.81	0.0003	98.74	1.00	52.73
23.50	0.23	-3.74	3.72	-173.45	0.0010	34.03	1.00	45.39
24.00	0.22	-20.84	4.67	171.42	0.0012	26.69	1.00	36.93
24.50	0.22	-38.46	5.89	153.98	0.0009	64.11	1.00	26.90
25.00	0.23	-56.48	7.47	134.19	0.0018	35.00	1.00	15.59
25.50	0.24	-74.69	9.29	111.36	0.0017	23.11	1.00	2.57
26.00	0.24	-92.54	11.07	86.85	0.0020	3.86	0.93	-11.48
26.50	0.25	-110.29	12.61	60.91	0.0028	-2.64	0.83	-25.69
27.00	0.25	-127.45	13.95	34.87	0.0030	-33.85	0.70	-40.01
27.50	0.26	-143.64	14.79	8.57	0.0034	-33.53	0.56	-52.60
28.00	0.25	-158.95	15.29	-17.59	0.0034	-46.81	0.43	-61.28
28.50	0.24	-173.35	15.27	-43.11	0.0019	-76.82	0.33	-63.93
29.00	0.22	171.21	15.04	-67.65	0.0023	-138.41	0.27	-60.16
29.50	0.19	155.15	14.71	-90.91	0.0029	-169.26	0.25	-54.40
30.00	0.15	138.97	14.44	-113.14	0.0042	173.19	0.26	-51.72
30.50	0.11	119.25	14.21	-135.14	0.0045	168.43	0.27	-53.13
31.00	0.05	89.26	14.12	-157.28	0.0050	138.57	0.30	-57.53
31.50	0.03	-10.38	14.03	-179.93	0.0066	110.64	0.33	-63.39
32.00	0.08	-63.92	14.02	156.67	0.0067	104.86	0.36	-71.39
32.50	0.14	-86.84	13.83	132.18	0.0074	104.16	0.40	-81.21
33.00	0.18	-103.57	13.45	106.66	0.0071	104.21	0.44	-91.19
33.50	0.21	-117.45	12.82	80.81	0.0071	116.13	0.48	-102.55
34.00	0.25	-129.30	12.12	53.53	0.0086	114.18	0.53	-114.85
34.50	0.26	-140.80	10.88	26.05	0.0100	99.52	0.55	-128.52
35.00	0.26	-149.75	9.50	-1.43	0.0112	90.23	0.55	-141.63
35.50	0.25	-153.15	8.12	-27.78	0.0099	72.51	0.54	-152.84
36.00	0.25	-156.29	6.90	-54.90	0.0141	24.34	0.50	-163.71
36.50	0.26	-151.97	5.53	-80.97	0.0137	8.68	0.46	-170.54
37.00	0.30	-149.76	4.37	-105.16	0.0128	-3.35	0.43	-175.21
37.50	0.36	-151.29	3.44	-126.85	0.0108	-11.68	0.43	-178.10
38.00	0.42	-156.26	2.71	-148.14	0.0046	-2.18	0.44	178.29
38.50	0.48	-162.95	2.14	-168.76	0.0019	54.40	0.44	173.94
39.00	0.52	-170.50	1.66	170.83	0.0036	74.41	0.44	170.08
39.50	0.56	-176.61	1.35	152.84	0.0051	78.45	0.44	166.96
40.00	0.59	178.86	1.17	138.10	0.0054	78.89	0.44	164.74

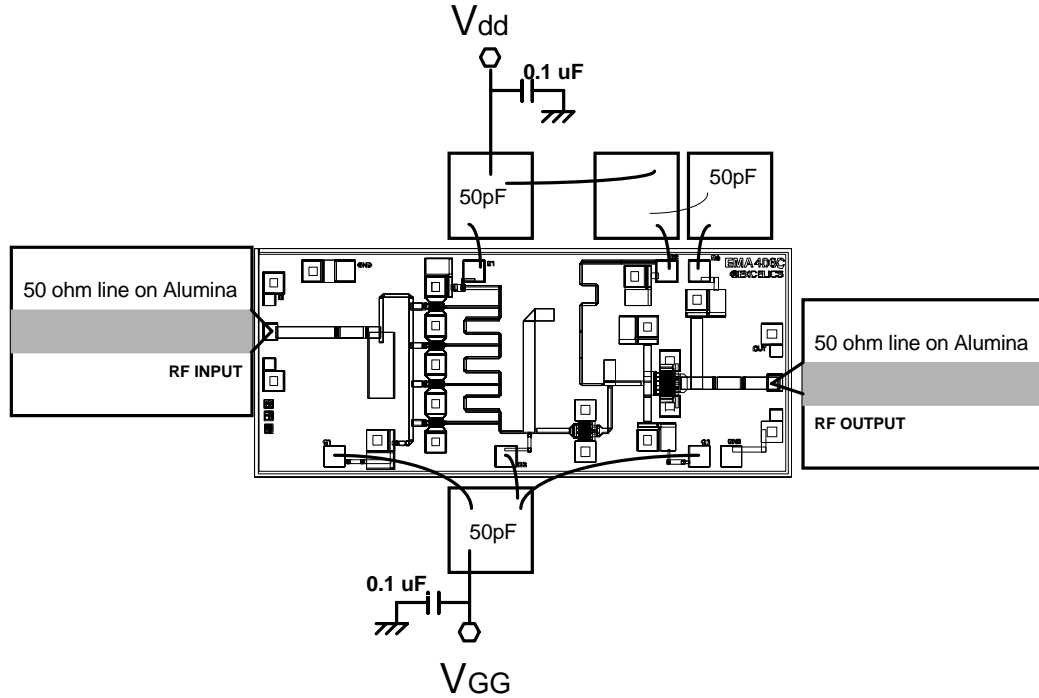


# EMA406C

## TENTATIVE DATA SHEET

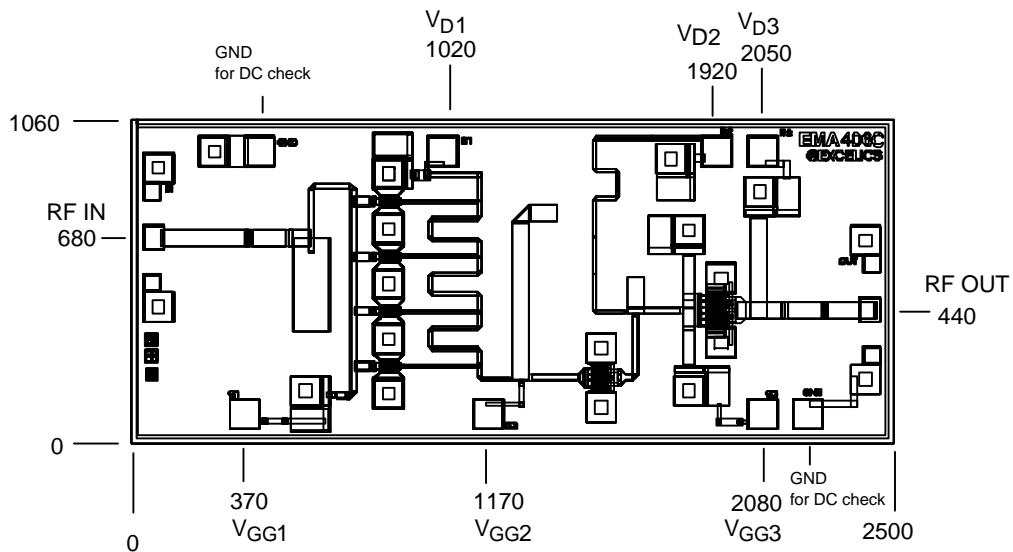
### 26 - 32 GHz Low Noise MMIC

#### ASSEMBLY DRAWING



The length of RF wires should be as short as possible. Use at least two wires between RF pad and 50 ohm line and separate the wires to minimize the mutual inductance.

#### CHIP OUTLINE



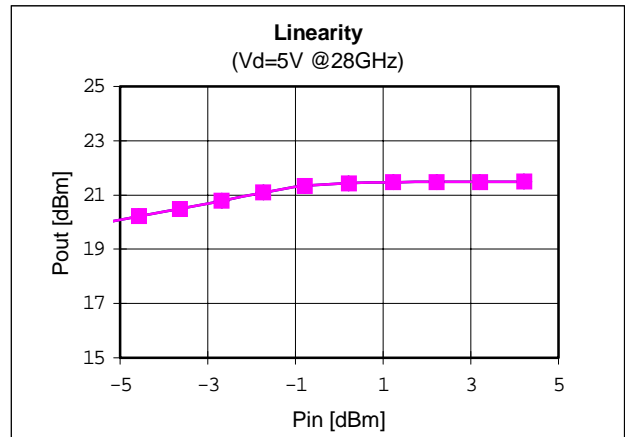
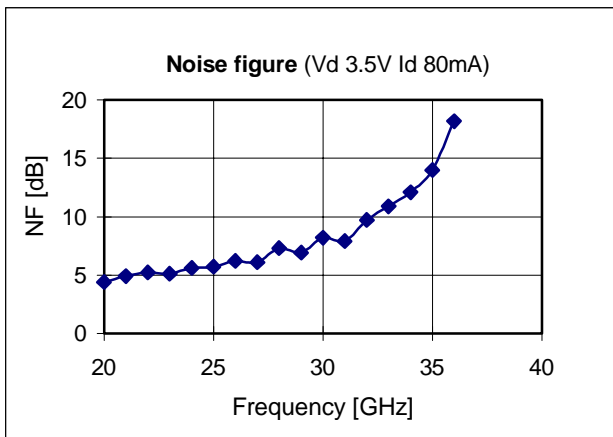
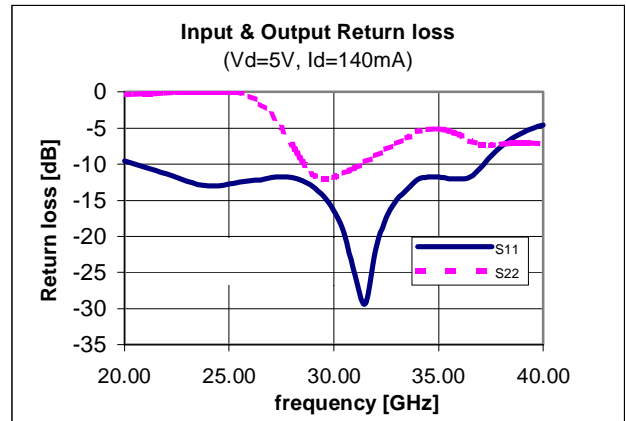
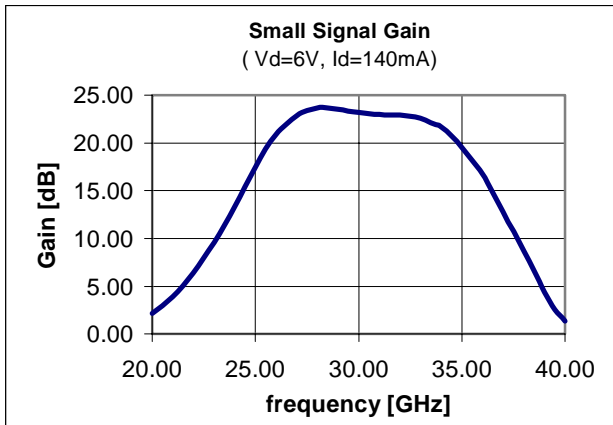
Chip Size 1060 x 2500 microns  
 Chip Thickness: 75 ± 13 microns  
 PAD Dimensions: 1. DC 100 x 100 microns  
 2. RF 80 x 68 microns  
 All Dimensions In Microns

# EMA406C

## TENTATIVE DATA SHEET

### 26 - 32 GHz Low Noise MMIC

#### TYPICAL APPLICATION PERFORMANCE

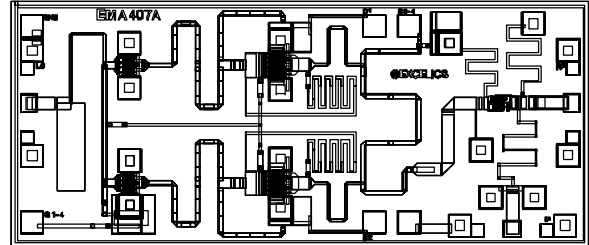


# EMA407A

## TENTATIVE DATA SHEET 20-32 GHz SUB-HARMONICALLY PUMPED MIXER

### FEATURES

- 20-32 GHz BANDWIDTH
- INTEGRATED LO AMPLIFIER
- 11 dB  $\pm$  1.5 dB TYPICAL CONVERSION LOSS
- 0.3 MICRON RECESSED “MUSHROOM” GATE
- Si<sub>3</sub>N<sub>4</sub> PASSIVATION
- ADVANCED EPITAXIAL HETEROJUNCTION



The EMA407A chip is a sub-harmonically pumped MMIC mixer with an integrated LO amplifier. It can be used as an up-converter or down-converter.

### ELECTRICAL CHARACTERISTICS<sup>1</sup> (T<sub>a</sub> = 25 °C)

SYMBOL	PARAMETERS/TEST CONDITIONS	MIN	TYP	MAX	UNIT
F <sub>RF</sub>	RF Frequency Range	20		32	GHz
F <sub>LO</sub>	LO Frequency Range	9		18	GHz
F <sub>IF</sub>	IF Frequency Range			5	GHz
P <sub>1dB</sub>	Input RF Power at 1dB Gain Compression		6		dBm
C <sub>L</sub>	Conversion loss		11		dB
Δ C <sub>L</sub>	Flatness		± 1.5		dB
NF	Noise Figure		11		dB
LO <sub>dr</sub>	LO drive level		8		dBm
I <sub>dd</sub>	Power Supply Current		160		mA
V <sub>dd</sub>	Power Supply Voltage		5	8	V

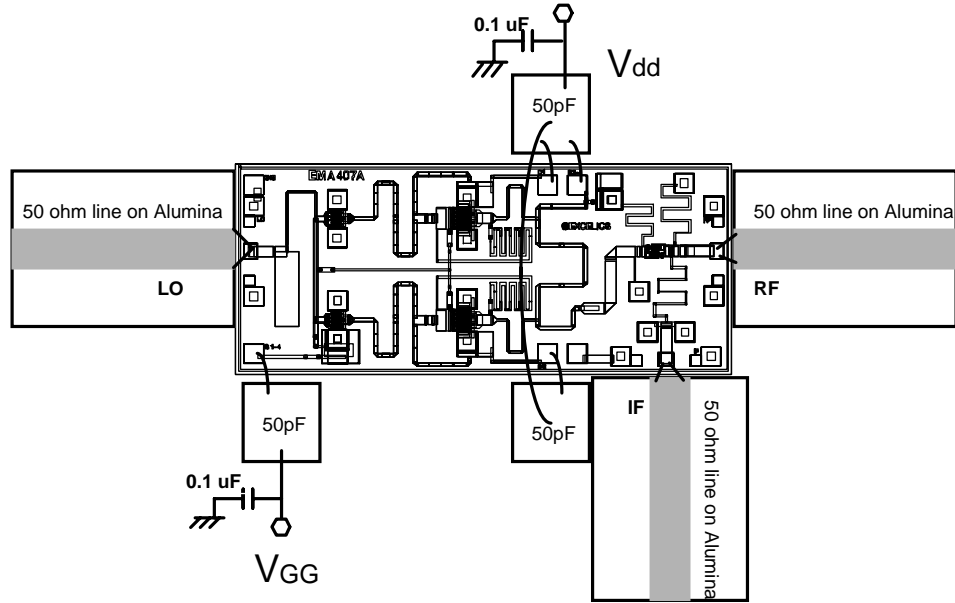
### MAXIMUM RATINGS AT 25°C

SYMBOLS	PARAMETERS	ABSOLUTE <sup>1</sup>	CONTINUOUS <sup>2</sup>
V <sub>ds</sub>	Drain-Source Voltage	12V	8V
V <sub>gs</sub>	Gate-Source Voltage	-8V	-3V
I <sub>ds</sub>	Drain Current	I <sub>dss</sub>	225mA
I <sub>gf</sub>	Forward Gate Current	55 mA	9mA
P <sub>in</sub>	Input Power	dBm	@3dB Compression
T <sub>ch</sub>	Channel Temperature	175°C	150°C
T <sub>stg</sub>	Storage Temperature	-65/175°C	-65/150°C
P <sub>t</sub>	Total Power Dissipation	1.1 W	900 mW

# EMA407A

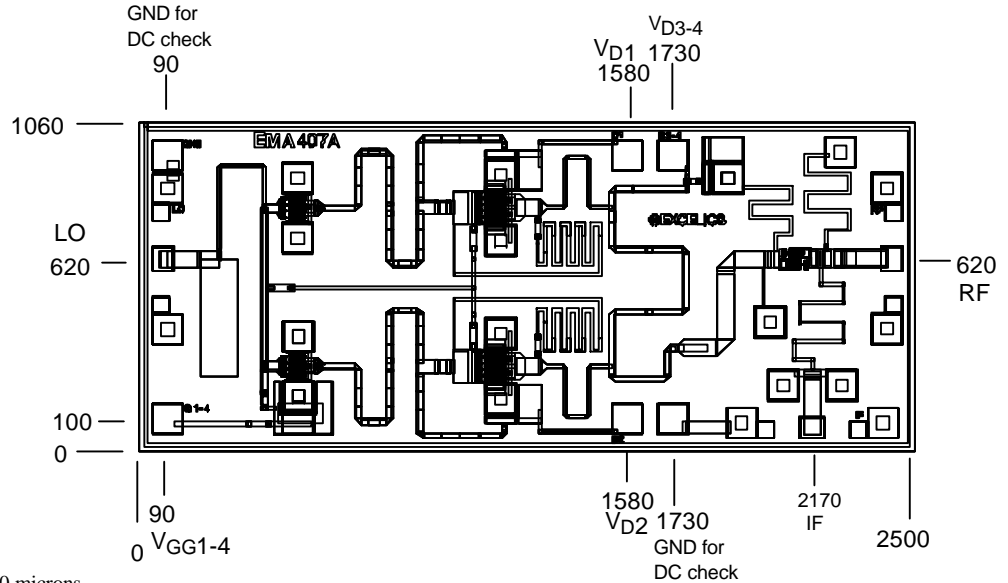
## TENTATIVE DATA SHEET 20-32 GHz SUB-HARMONICALLY PUMPED MIXER

### ASSEMBLY DRAWING



The length of wires for RF and LO connections should be as short as possible. Use at least two wires, and separate the wires to minimize the mutual inductance.

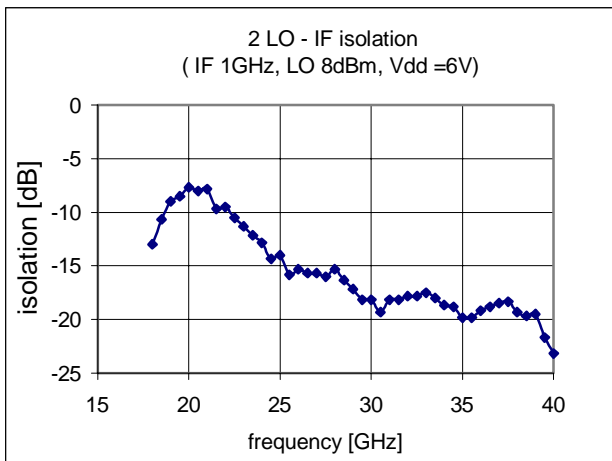
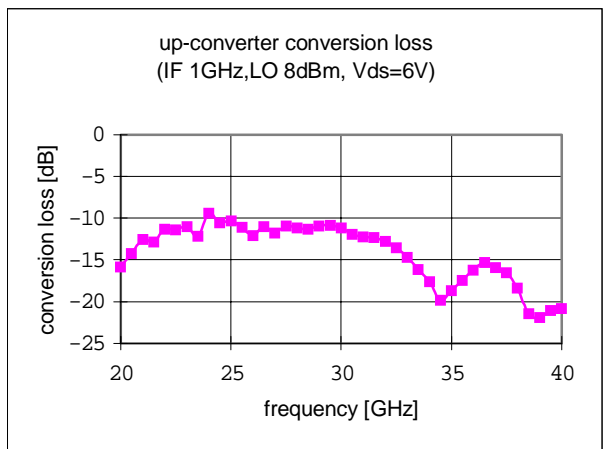
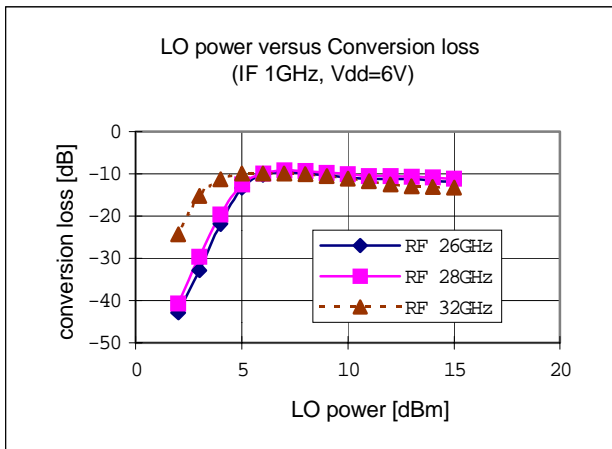
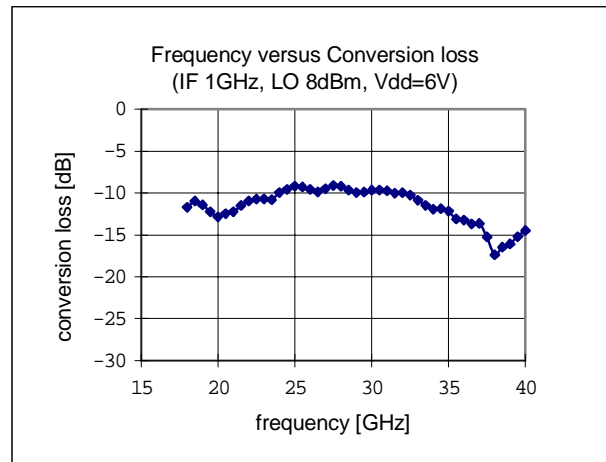
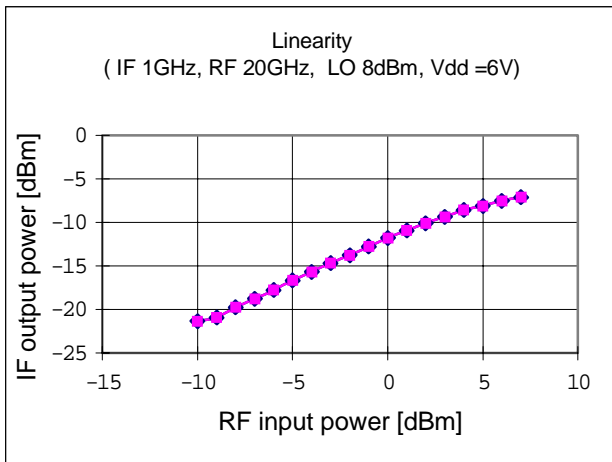
### CHIP OUTLINE



Chip Size 1060 x 2500 microns  
 Chip Thickness:  $75 \pm 13$  microns  
 PAD Dimensions: 1. DC 100 x 100 microns  
 2. RF 80 x 68 microns  
 All Dimensions In Microns

## TENTATIVE DATA SHEET 20-32 GHz SUB-HARMONICALLY PUMPED MIXER

### TYPICAL APPLICATION PERFORMANCE



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## TENTATIVE DATA SHEET 20-32 GHz SUB-HARMONICALLY PUMPED MIXER

### APPLICATION HINTS

The device should be die attached with Gold-Tin eutectic. Epoxy die attach is not recommended. Thermocompression bonding of .7 mil to 1 mil diameter gold wire is recommended.

The sources of the transistors are directly via-hole grounded. A negative voltage is required to bias the gates of the transistors. The gate voltage for the input stage must be provided at the RF input bonding pad, and the drain current for the output stage must be provided through the output bonding pad. The drain bias circuits should be well bypassed down to MHz frequencies to prevent oscillations. Some isolation should be provided between the two drain circuits at GHz frequencies to prevent oscillations. Although there is some bypassing on chip of the VD1 and VG2 terminals, additional bypass capacitors, placed close to the chip, are recommended.

The gate and drain power supplies should be sequenced to turn on the negative gate voltage before the positive drain voltage is applied. Turning on the full drain voltage before the gate voltage can cause excessive power dissipation or destructive oscillations.



# 电子元器件系列

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